

LIGHTWAVE LOGIC™

OTCQB: LWLG

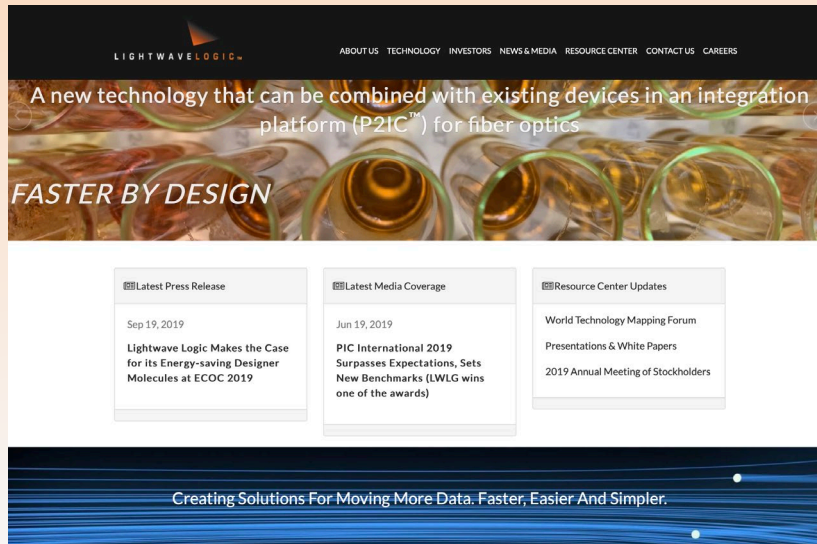
ECOC Market Focus:

“Polymer modulators with >50GHz performance for power consumption reduction at 400, 800, and 1600 Gbaud aggregated datarates”

Michael Lebbby
CEO Lightwave Logic Inc

The information in this presentation may contain forward-looking statements within the meaning of the Private Securities Litigation Reform Act of 1995. You can identify these statements by use of the words "may," "will," "should," "plans," "explores," "expects," "anticipates," "continue," "estimate," "project," "intend," and similar expressions. Forward-looking statements involve risks and uncertainties that could cause actual results to differ materially from those projected or anticipated. These risks and uncertainties include, but are not limited to, general economic and business conditions, effects of continued geopolitical unrest and regional conflicts, competition, changes in technology and methods of marketing, delays in completing various engineering and manufacturing programs, changes in customer order patterns, changes in product mix, continued success in technological advances and delivering technological innovations, shortages in components, production delays due to performance quality issues with outsourced components, and various other factors beyond the Company's control.

Slide presentation will be posted at website



www.lightwavelogic.com

Sit back...relax...

Agenda

- Key trends
- Target Markets: large & facing a growing gap
 - Market environment
 - Market gap
- Market technology opportunities
 - Faster devices,
 - Lower power,
 - Lower cost,
 - Robustness
- Roadmap update
- Summary

NB: These green bars give a summary of each slide



Warning: Traffic jams on the information superhighway

- Network cost and energy have become the new hot spot for data providers. This is the problem we seek to address.

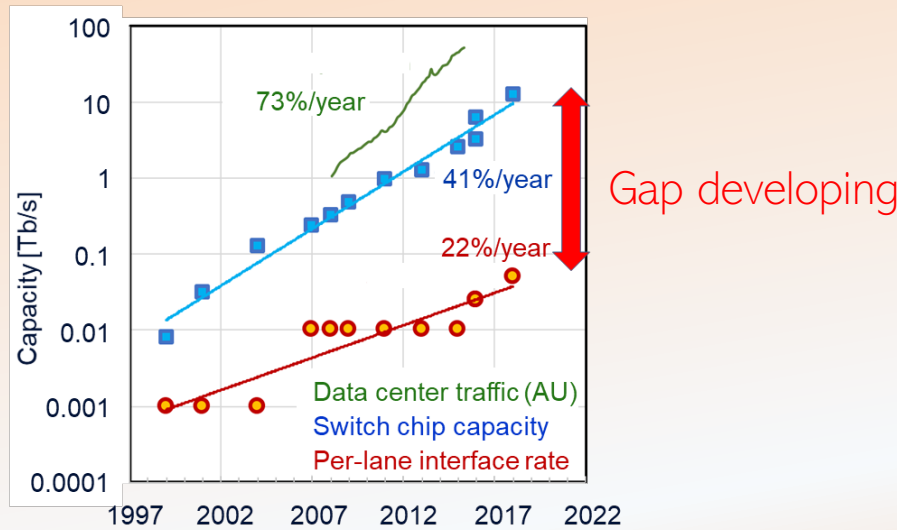


Cost and energy are now focus areas...



The problem is the speed limit of the optics...

- The Network is falling behind the traffic growth



Source: Peter Winzer, Nokia, "Scaling Optical Networking Capacity: Options and Solutions"



Huge data volumes are enabled by **low cost and energy** for computation and storage. Thank you Moore's Law for semiconductors.

The big data pipes inside datacenters, between datacenters, and from datacenters to end-users are **fiber optic**. The problem? No Moore's Law for optics.

Radical innovation is needed...

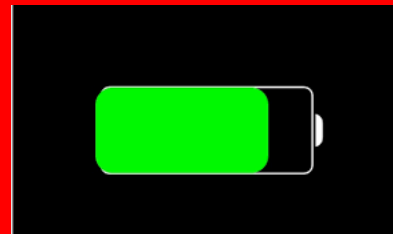
Delivering radical innovation...

Photonics must deliver solutions:

Faster devices
(100GHz+)



Lower Power
(Low voltage)



Lower cost
(Easy fab)



Robust
(Stable)



To enable faster, lower power, lower cost internet...



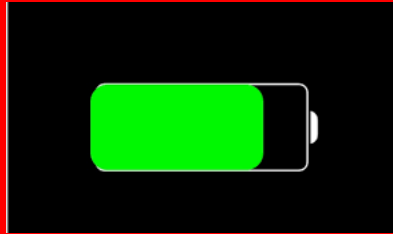
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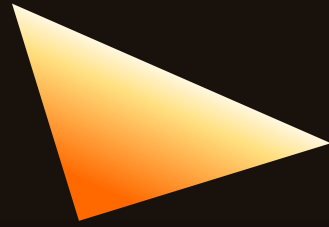
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Faster devices...

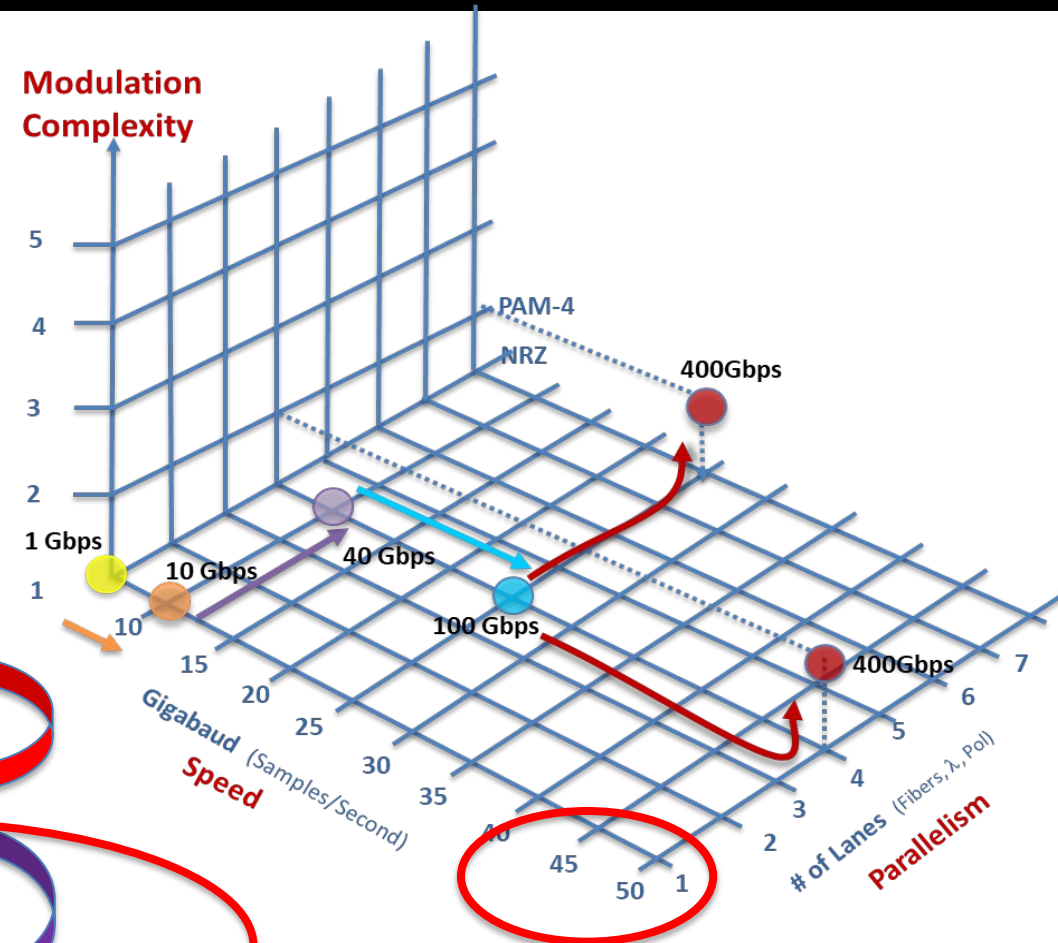




But the internet has been growing
fine, so what's changed?

Historical perspective

- 1 Gbps: 1 lane x 1 Gbps (1990s) → Easy
 - 10 Gbps: 1 lane x 10 Gbps (circa 1999-2000) → Tougher
 - 40 Gbps: 4 lane x 10 Gbps (early 2000s) → Tougher
 - 100 Gbps: 4 lane x 25 Gbps (early 2010s) → Difficult
 - 400 Gbps: 4 lane x 50 Gbps PAM4
 400 Gbps: 8 lane x 25 Gbps PAM4 (2015 onwards) → Much more difficult
- 800 Gbps
1600 Gbps



Things get tougher with increasing data rates

Traffic capacity: road analogy

Good roads: Faster cars:
more traffic capacity



More lanes: more traffic capacity



Already did the easy things like paving the road and adding more lanes

Traffic handling: road analogy



Industry has already done the **harder stuff** like 'higher order modulation'

What about speed?



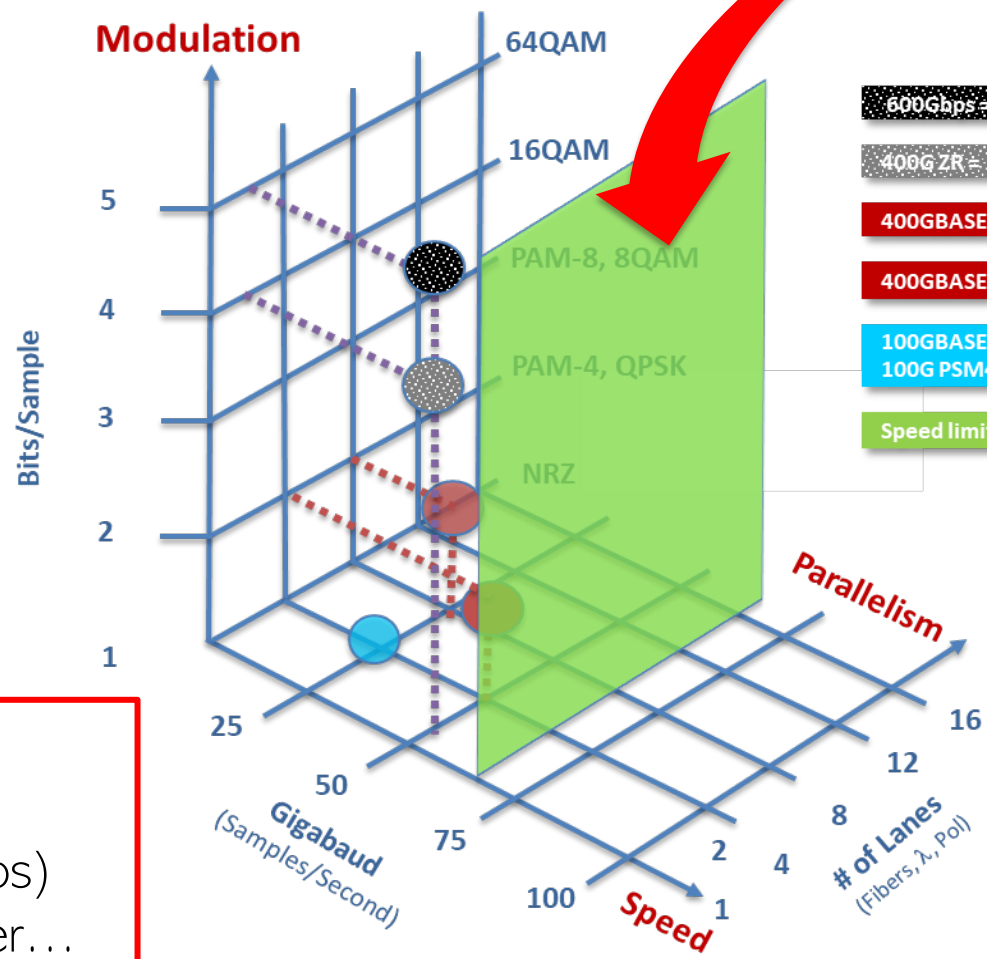
10 mph → 60 mph



Still ~60 mph

Speed has hit a plateau...

Speed limited by conventional photonics



- 600Gbps = 64 Gbaud, 64QAM, 2 polarizations
- 400G ZR = 50Gbaud, 16QAM, 2 polarizations
- 400GBASE-DR4/ 400G FR4= 50 Gbaud, PAM4, 4 wavelengths
- 400GBASE-LR8= 25 Gbaud, PAM4, 8 wavelengths
- 100GBASE-LR4/100G CWDM4 = 25 Gbaud, NRZ, 4wavelengths
- 100G PSM4 = 25 Gbaud, NRZ, 4 fibers
- Speed limitation of optical devices

50 Gbaud is very difficult for conventional optical devices

In optical analog metrics of GHz, >35GHz (50Gbps) things get tougher...

Speed limited by device physics



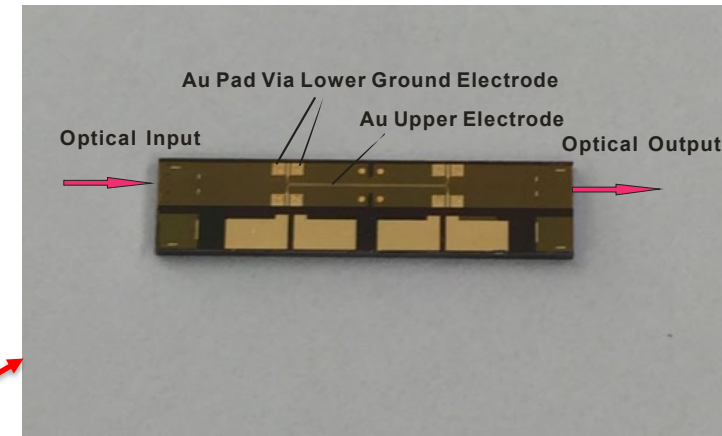
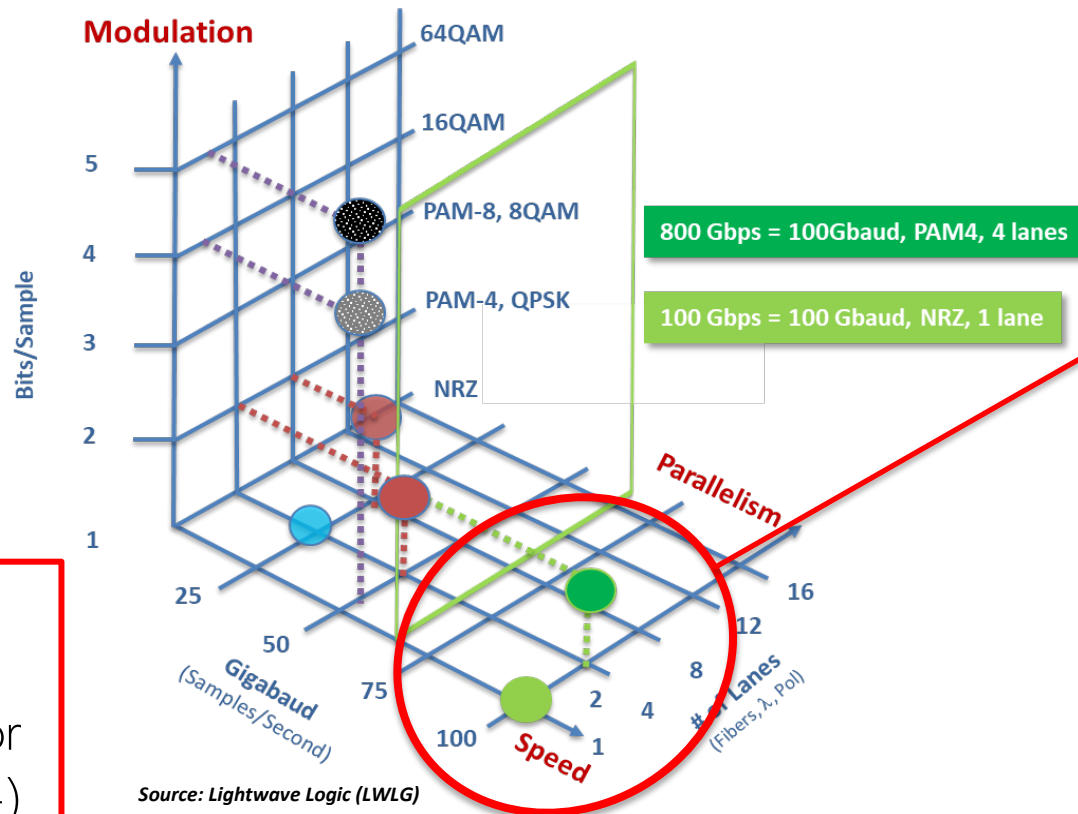
Plastic polymers break the speed limit...



Polymers are faster than other technologies

Polymers double the native data traffic to 100Gbps (before counting multiple lanes, stacking...)

Innovation to break the speed barrier



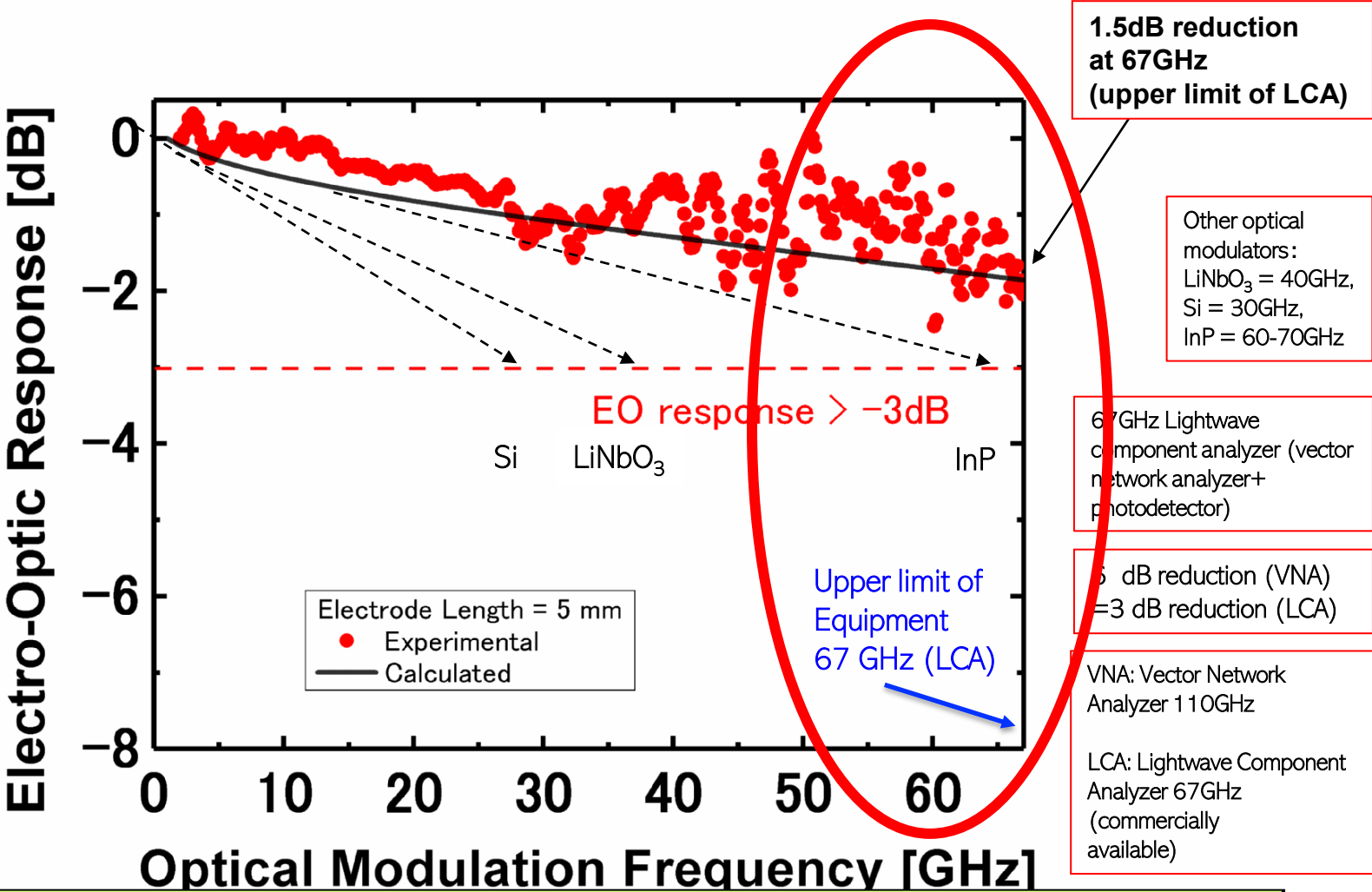
- Options can be:
- 100G, 1V
 - 100Gbaud, NRZ, OOK
- 400G, 1V
 - 4 Channel x 100G NRZ, OOK
- 800G, 1V
 - 4 Channel x 100G, PAM-4

In optical analog metrics $\sim 70\text{GHz}$ (100Gbps, NRZ or 200Gbaud, PAM4) is a challenge

Renewed ability to grow traffic capacity



Electro-Optic Response on Lightwave Component Analyzer



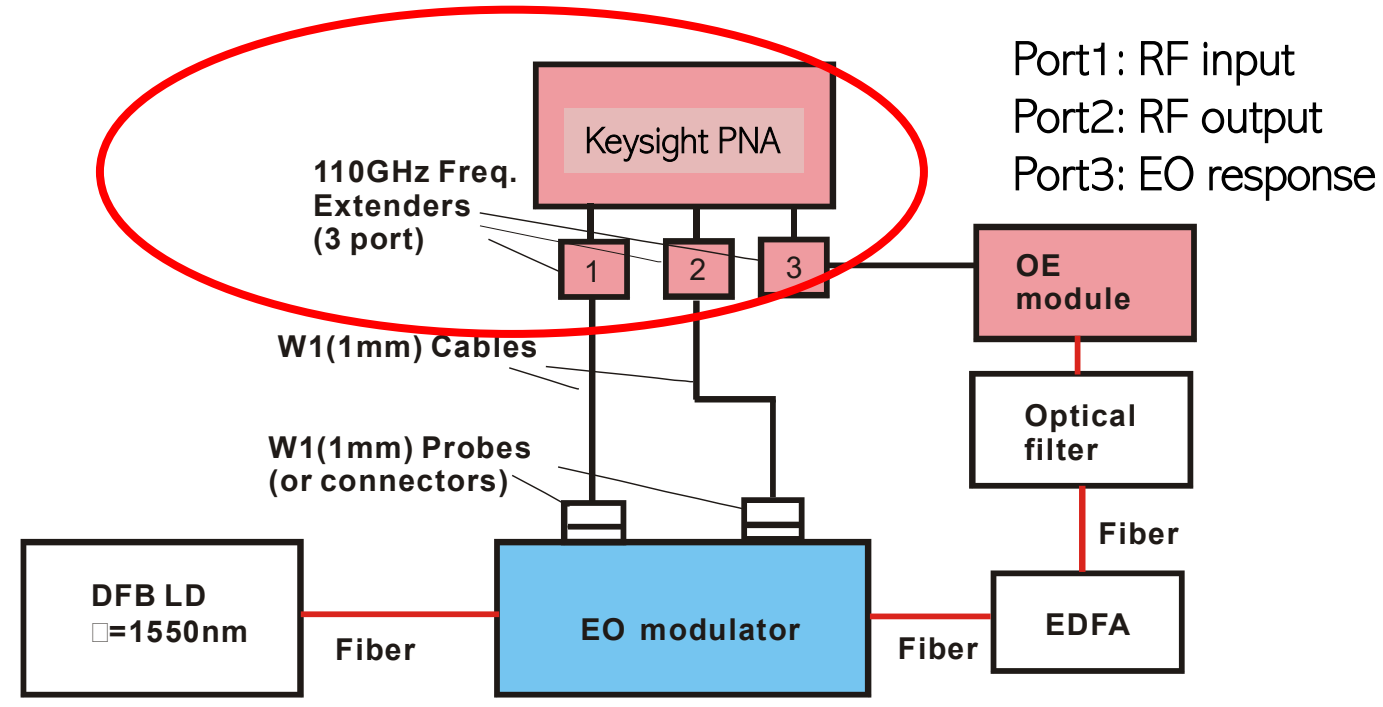
In optical analog metrics ~70GHz is more than the equipment can handle...

Extrapolated 3dB bandwidth of ~120GHz for EO response

Source: Lightwave Logic (LWLG); Yasufumi Enami (University of Kochi, Japan; University of Arizona)



EO frequency response measurements



Port1: RF input
 Port2: RF output
 Port3: EO response

New equipment for 110GHz optical analog bandwidth: designs can be optimized

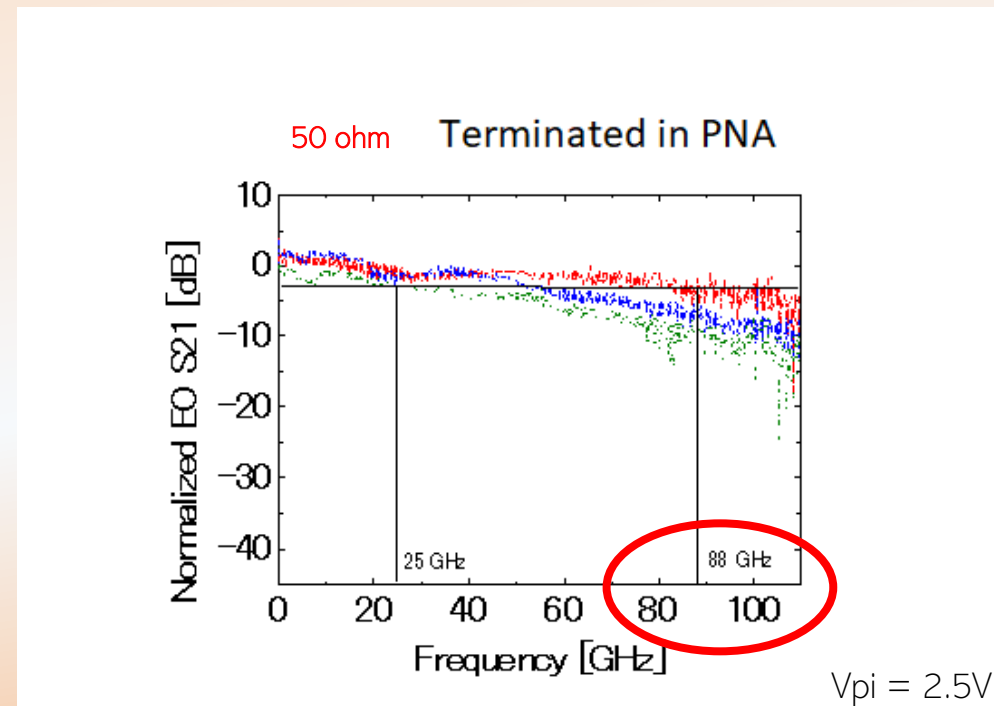
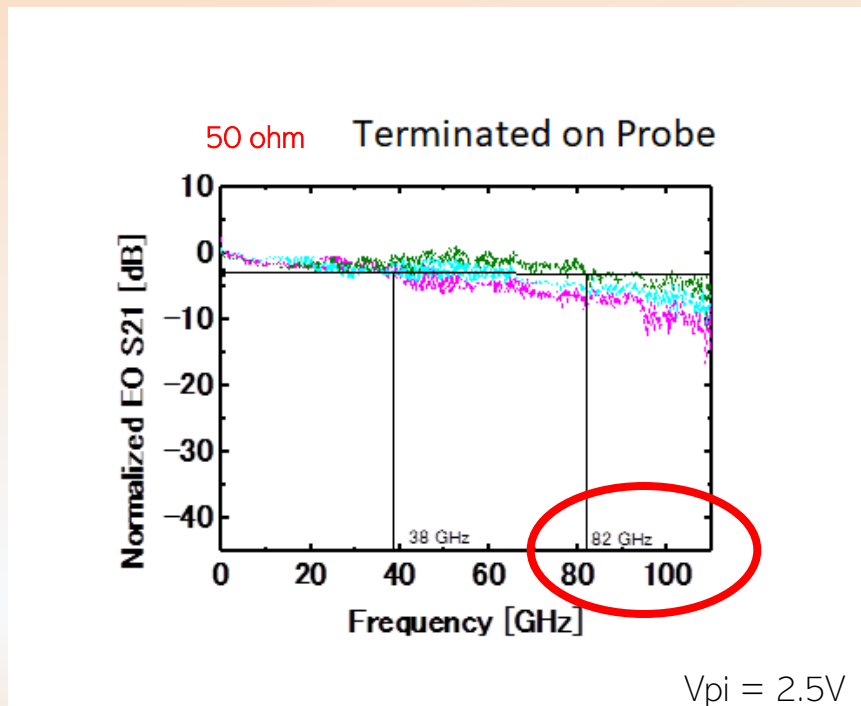
PNA: Vector network analyzer
 EDFA: Er doped fiber amplifier
 OE : Opto-electric
 DFB LD: Distributed feedback laser diode

Port 1 and 2 for EE S21 and S11
 Port 1 and 3 for EO S21

State-of-the-art 110GHz measurement set-up

EO Polymer RWG Modulator

- Polymer modulator analogue optical bandwidth



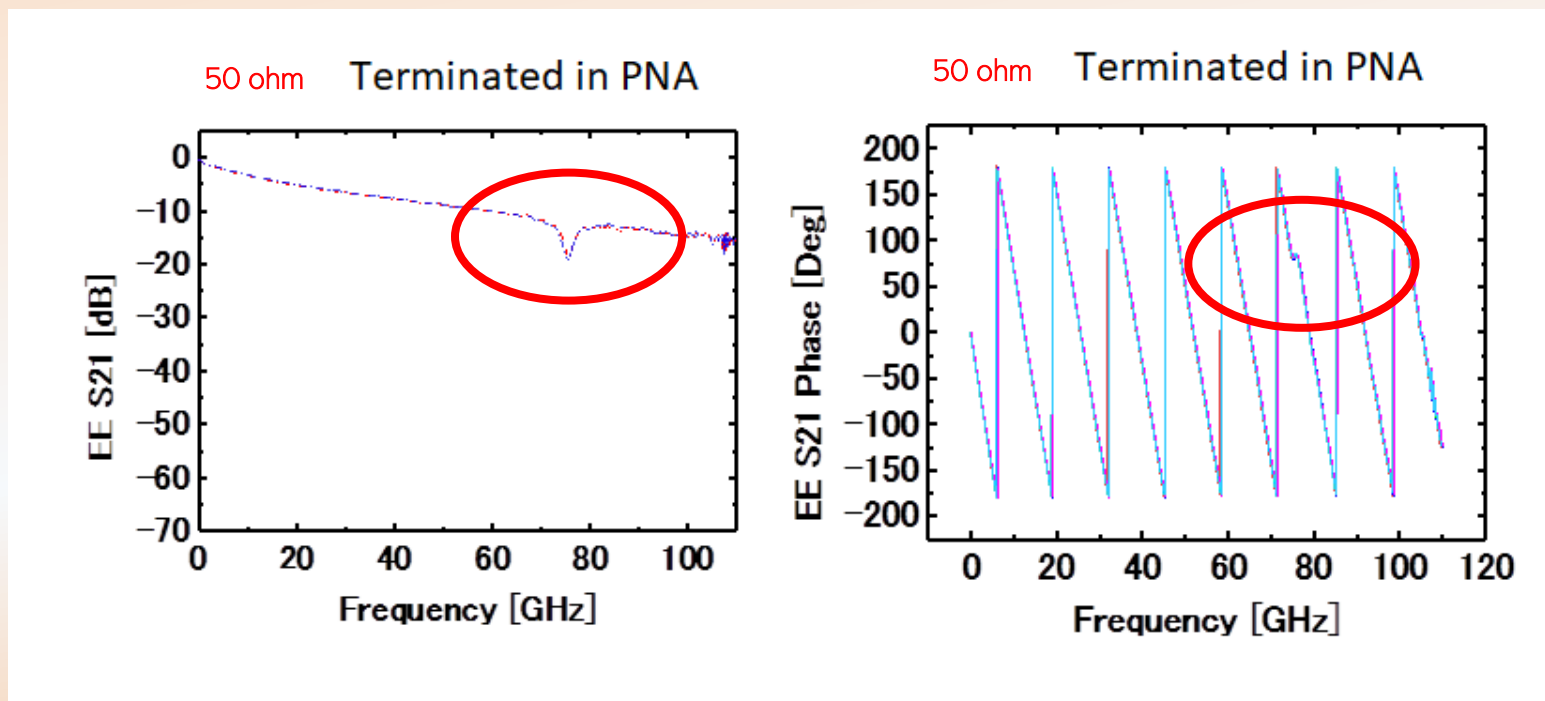
Measurement at >70GHz is very sensitive



Electrical characterization

- EE S21 linear magnitude and phase
 - With small calibration glitch at ~75GHz

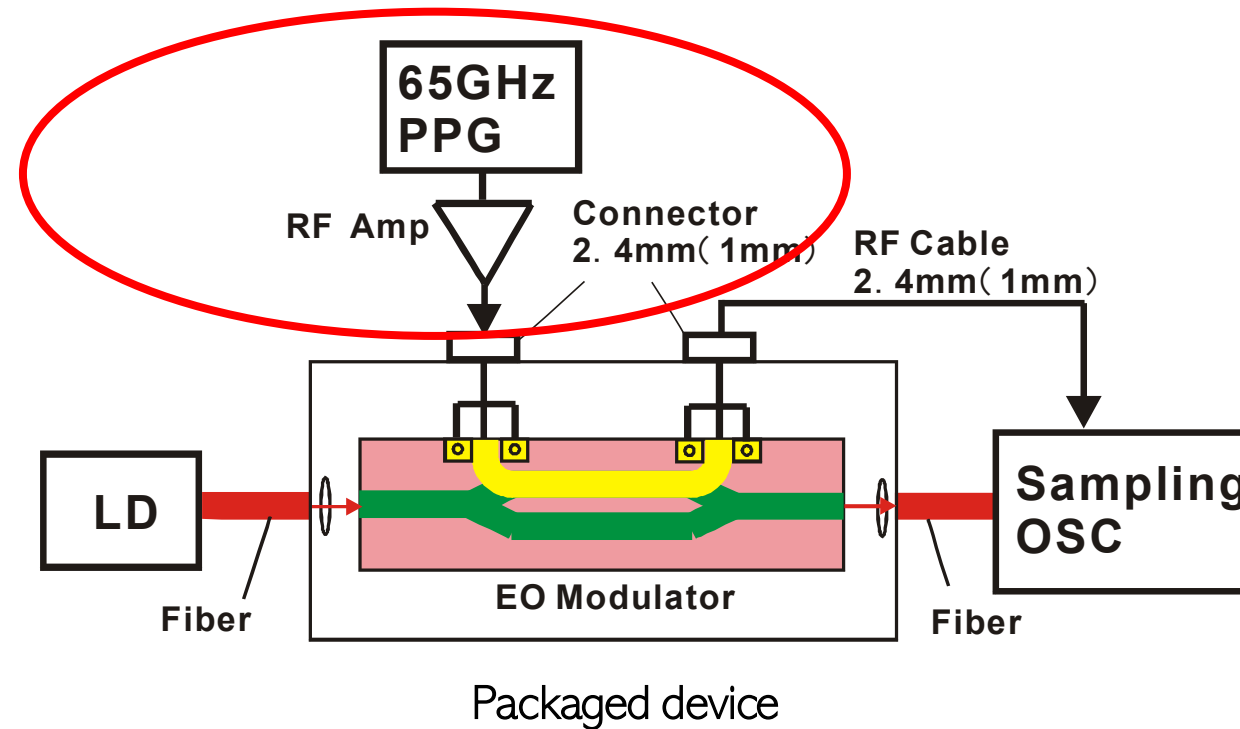
EE S21 magnitude response is very smooth and predictable



EE S21 phase response is very linear and predictable

Smooth EE S21 magnitude

Eye diagram measurements



Packaged devices group A : 1mm and 2.4mm connectors
Packaged devices group B : 2.4mm connectors

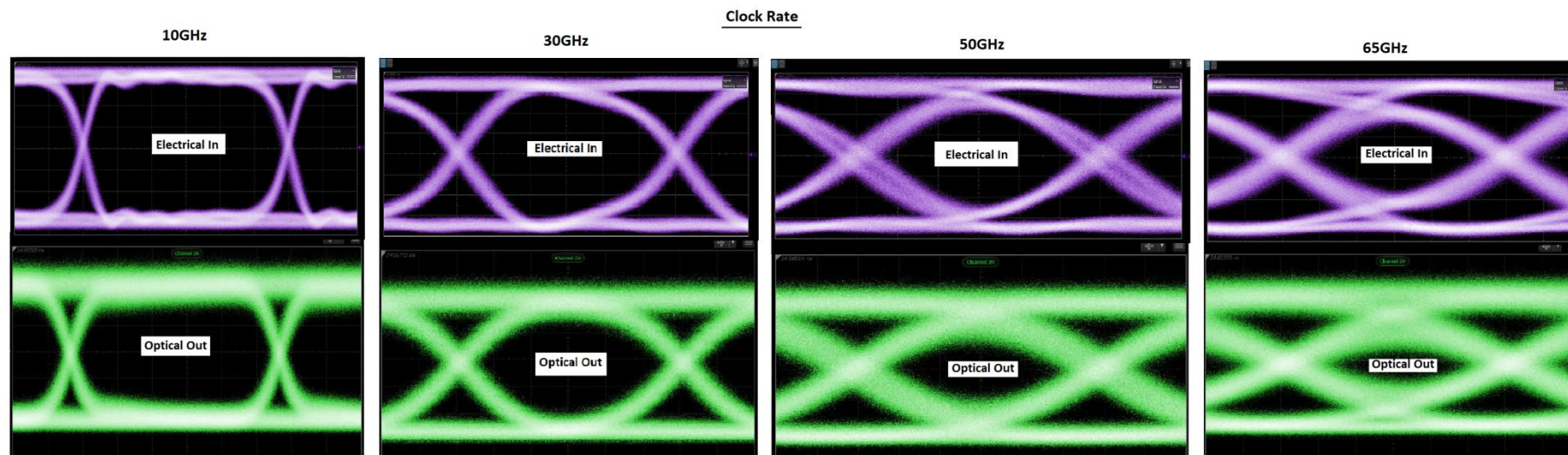
LD: Laser diode
PPG: Pulse generator (BERT)
OSC: oscilloscope

Packaged modulator set-up



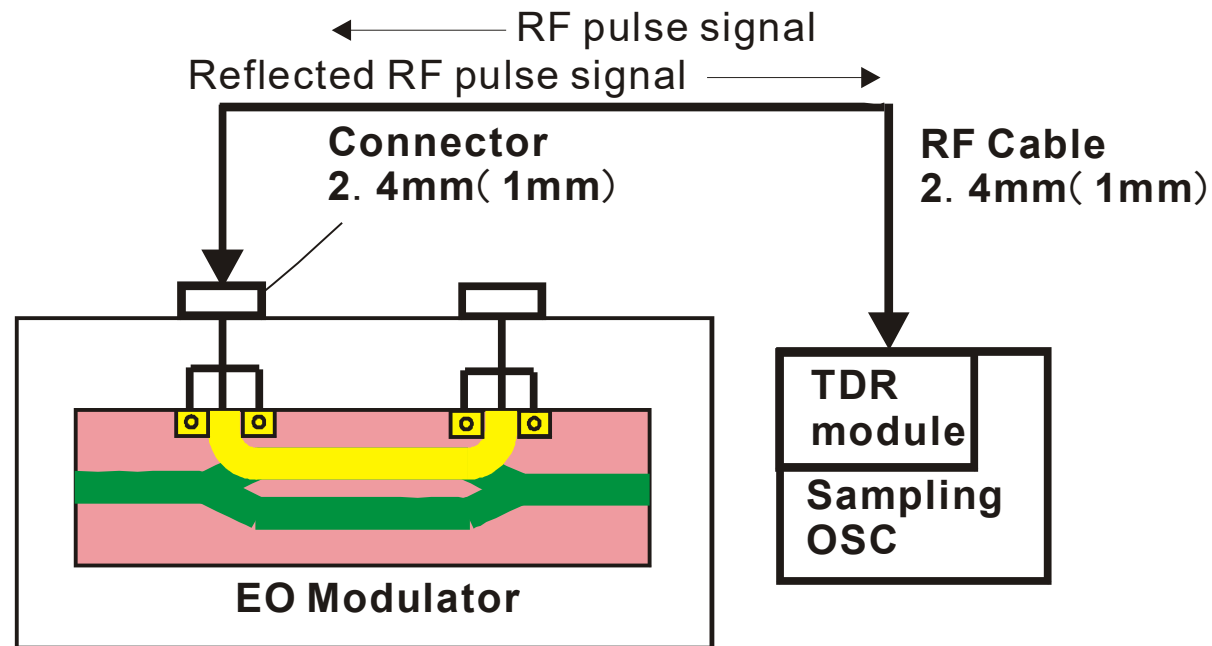
Eye diagram status

- Using DCA/BERT system
- Careful measurements of packaged polymer MZ
- Optical eyes follow input electrical signal well
- Open eyes at 65GHz (NRZ)



Eye diagram partly limited by input signal

TDR measurement capability review



Packaged devices group A : 1 mm and 2.4mm connectors

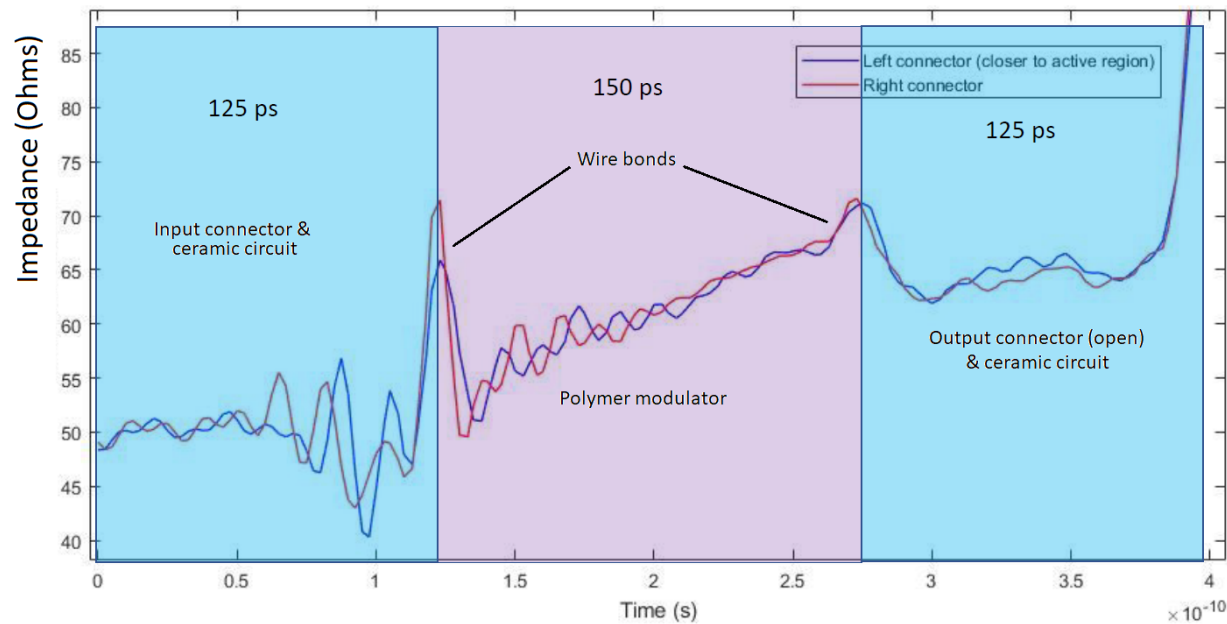
Packaged devices group B : 2.4mm connectors

TDR: Time domain reflectometry
Examine impedance matching in packaged device

Checking measurement capability through reflected signaling

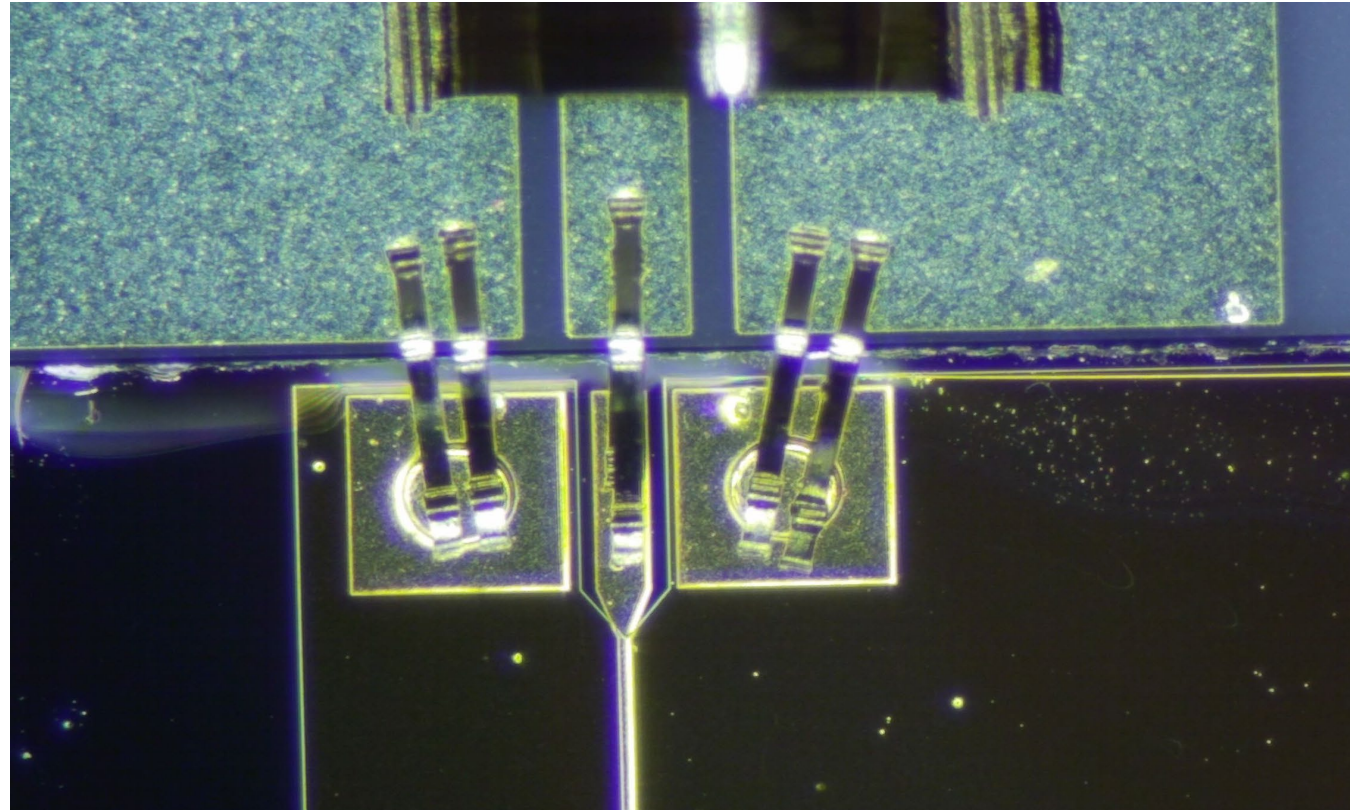
TDR to check measurement capability

- Using TDR from Keysight
- TDR measurements allows the determination of impedance discontinuities along the rf path and assists in making improvements
- TDR measurements show reflections that need to be optimized



TDR response to check measurement capability

Bond-ribbon Termination



TDR helps reduce reflections and allows improved designs

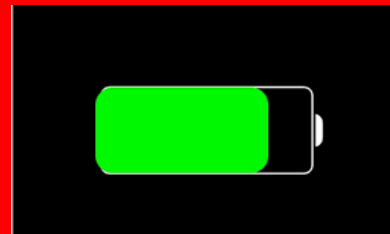
Delivering radical innovation...

Photonics must deliver solutions:

Faster devices
(100GHz+)



Lower Power
(Low voltage)



Lower cost
(Easy fab)



Robust
(Stable)



To enable faster, lower power, lower cost internet...



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Lower power

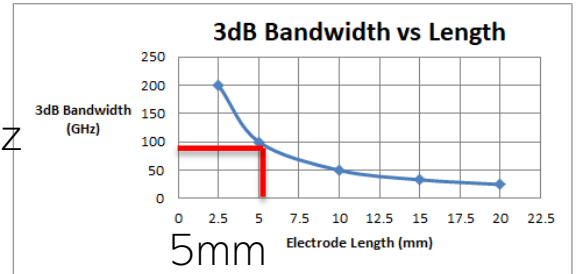




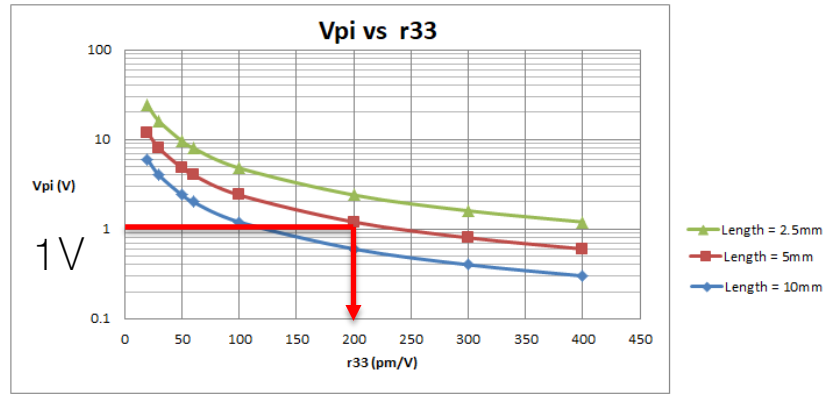
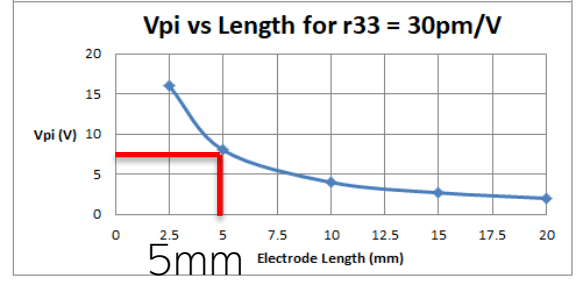
Importance of Larger r_{33}

- Frequency response is inversely proportional to electrode length
 - Shorter electrode → More Gbps
- BUT V_{pi} is **ALSO** inversely proportional to electrode length
 - Shorter electrode → Larger V_{pi}
- Only free variable is r_{33}
 - Larger r_{33} → Shorter electrode → More Gbps → Same or Smaller V_{pi}

80+GHz



6-7V



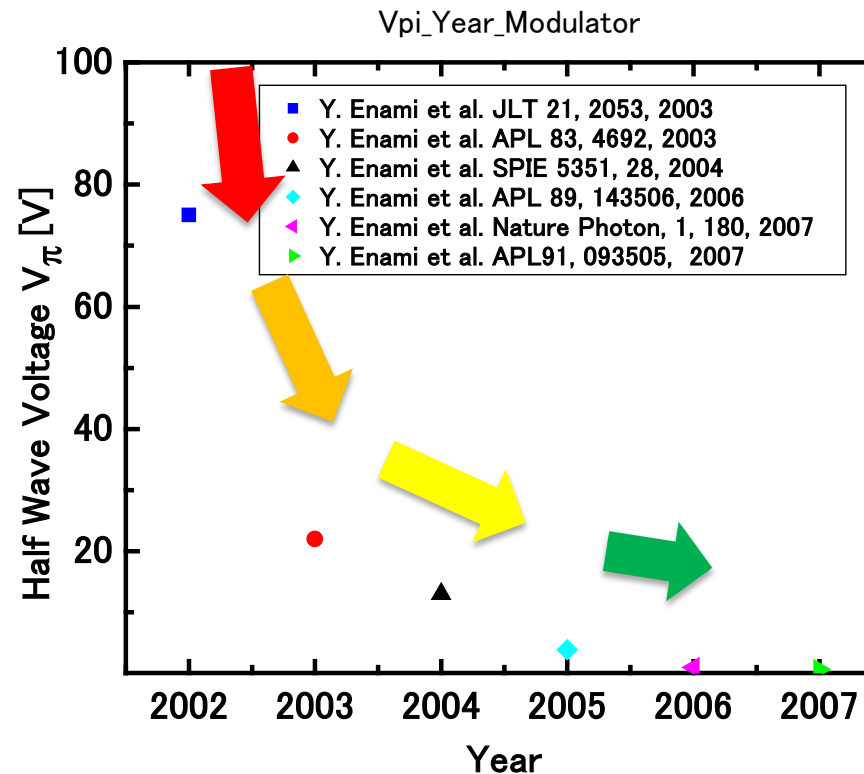
~200pm/V

Large r_{33} is key to high performance and low voltage



Direct drive CMOS → saves power

- Lower voltage operation save power
- Also means the modulators can be driven directly from a CMOS chip
- No driver chips necessary
 - Saves even more power
 - Also saves \$\$\$



Source: Lightwave Logic (LWLG); Yasufumi Enami (University of Kochi, Japan; University of Arizona)

Polymer modulators are *driverless, low power, and save \$\$\$*



Delivering radical innovation...

Photonics must deliver solutions:

<p>Faster devices (100GHz+)</p>	<p>Lower Power (Low voltage)</p>	<p>Lower cost (Easy fab)</p>	<p>Robust (Stable)</p>

To enable faster, lower power, lower cost internet...



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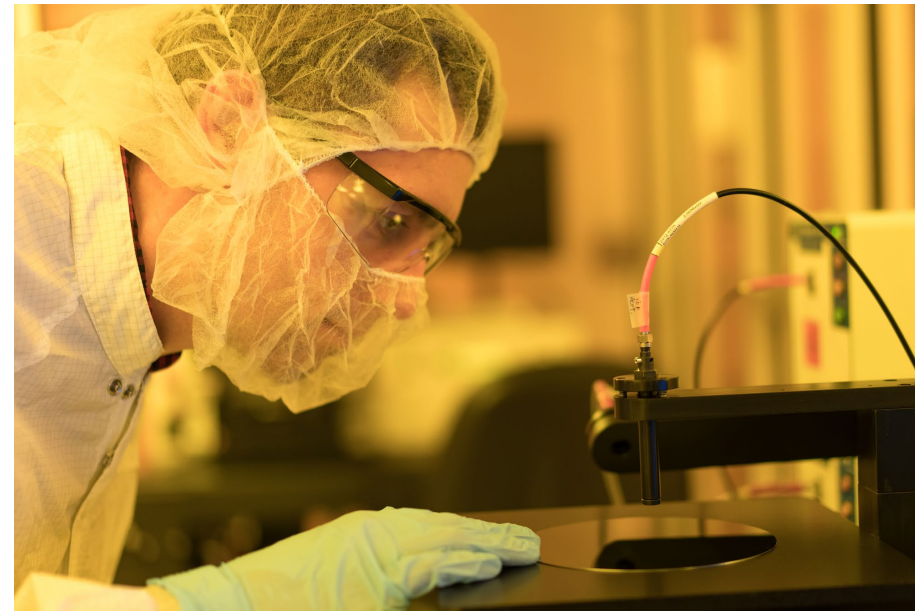
Lower cost...



Simple, low cost fabrication

Fabrication equipment and process is simple

- No exotic equipment needed
 - Standard photolithography to pattern
 - Wafer scalability
 - Minimize cycle time



Lower costs can be enabled through simplicity in fabs



Our competitive advantage starts with our materials

- Our Perkinamine™ family of materials are proprietary and we control the synthesis in-house.
- We have additional advantages through control of the whole stack—from materials to device and package designs. This synergy gives us more knobs with which to optimize performance and cost.

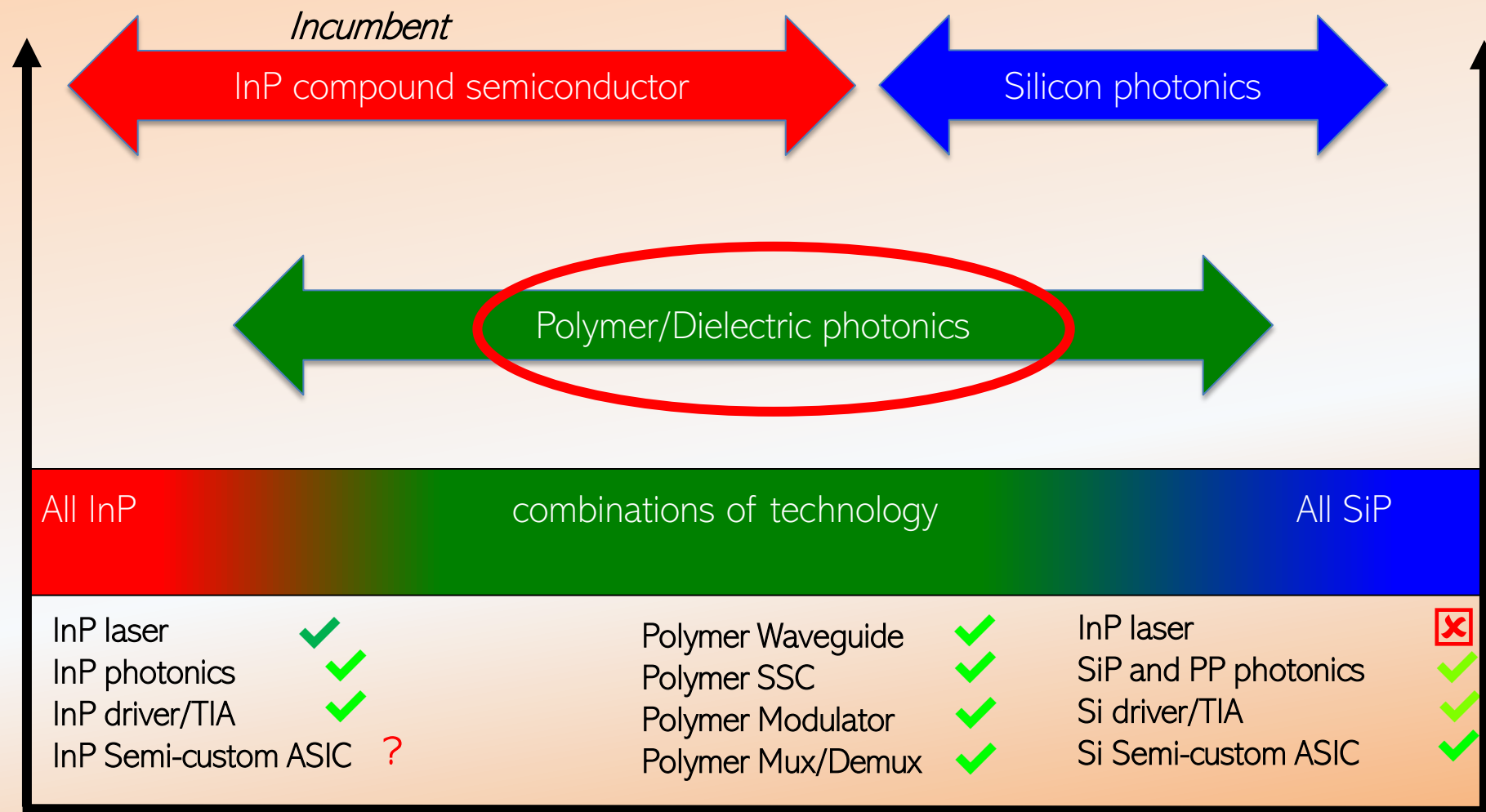


**Our active molecules are of similar complexity to medical drugs
Their performance characteristics can be tailored for each application**

Lower costs can be enabled through chemistry design



Integrate platforms → Hybrid solutions



Lower costs enabled through integration of hybrid technologies

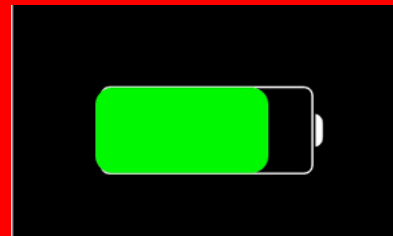
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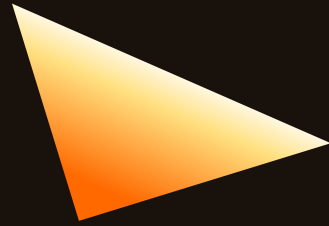
Lower cost
(Easy fab)



Robust
(Stable)



To enable faster, lower power, lower cost internet..



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Robust...



PIC semiconductor robustness/reliability

- Telecommunications always relied on Telcordia testing (GR-468 etc)
 - 10-20 year lifetime, low FIT rates, accelerated testing
- Datacommunications (datacenters) looked at simplifying R&QA to reduce cost
 - Recent datacenter requirements proposed 3yr fork-lift equipment changes, and reduced R&QA expectations
 - Today's datacenter folks are now looking to re-establish high reliability testing to reduce failure rates from 1000s of photonics equipment
- Net net → R&QA is still critical and needs to be taken very seriously
 - Next generation PICs must aim towards Telcordia requirements

R&QA needs to be aimed between datacom and telecom today



Electro-optic polymers have a negative perception

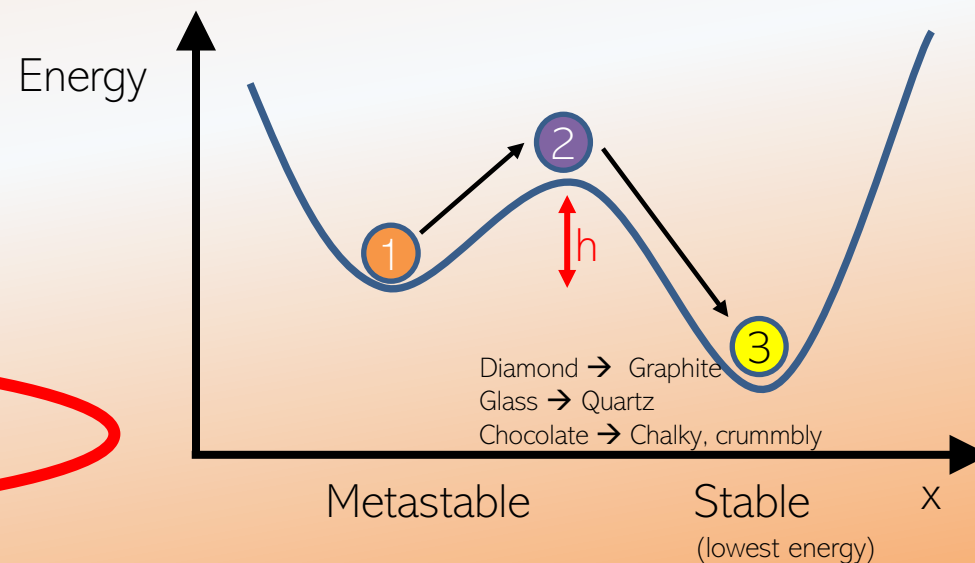
- Universal agreement on the EO performance of poled polymers
 - For example: 100GHz BW, Velocity match, Low V_{pi} , High r_{33} ...
- Universal *skepticism* on the stability of that performance.
 - “Organic isn’t as stable as inorganic”
 - The same arguments were made against LCDs and OLEDs also...
- A key technical challenge facing EO polymers:
 - *Stabilizing the meta-stable state...*

Stability is one of the keys to build positive perception in polymers



Stabilizing a meta-stable state

- The lowest energy state **3** is for all the snow to be at the bottom of the mountain. The system will relax (spectacularly) from **1** to **3** if sufficient energy (h) is applied.
- Yet we ski down mountains safely all the time because ski resorts can manage the barrier height of h :
 - Avalanche h can be set off by; skier triggering, sound, mortar, ski patrol
- Many materials we encounter every day are metastable (e.g., diamonds, glass, chocolate)
- Metastability is not something to avoid, but rather control...
- We've engineered polymers to be more stable in a meta-stable state



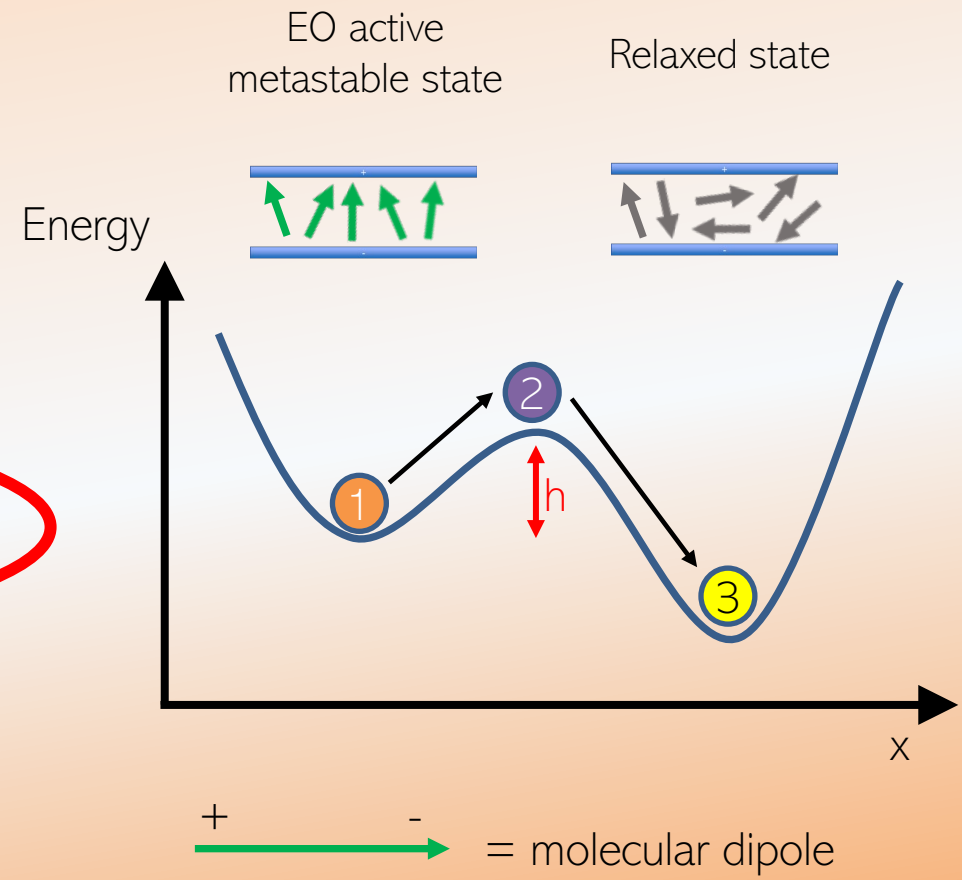
Engineering polymers for stability in a meta-stable state



Engineering the barrier height for stability

- Poled polymers will slowly relax to **3** at a rate controlled by barrier height **h**
- Engineering challenge is to make barrier **h** large
- No laws of physics need to be broken...

h can be controlled by careful molecular design and the power of synthetic organic chemistry

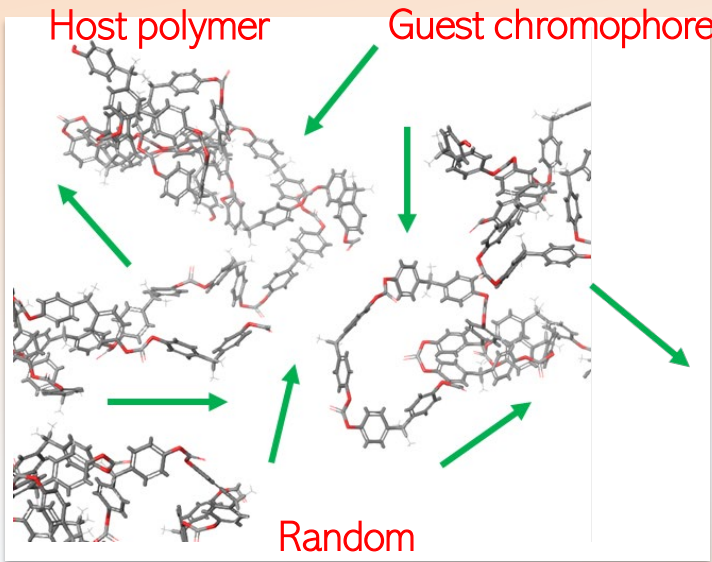


Barrier **h** can be engineered by molecular design

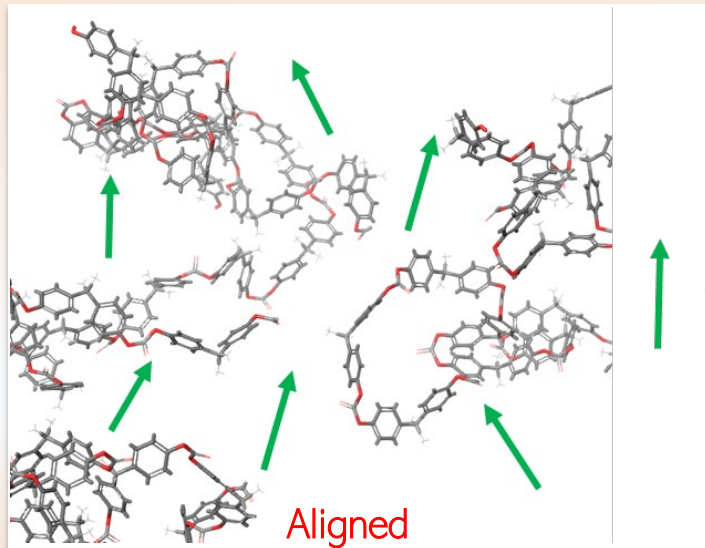


Optimizing the molecular design for stability

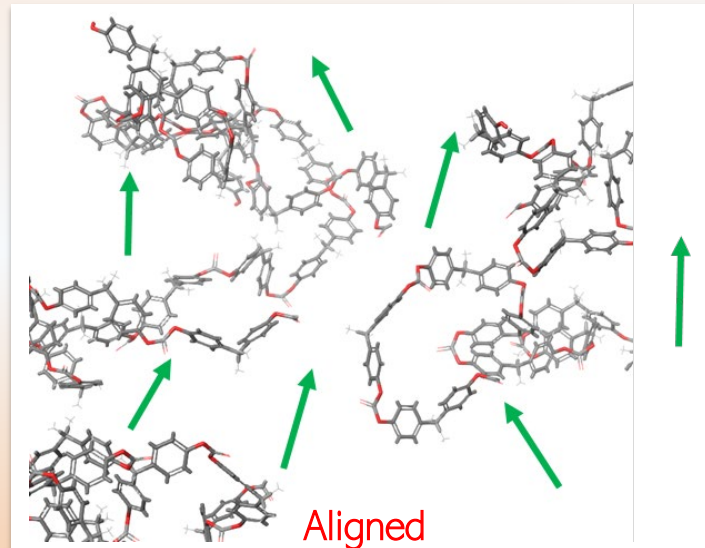
- The higher the rigidity of the polymer composite, the higher barrier h is (more stable)
- The more surrounded the chromophore dipoles are, the higher barrier h is (more stable)



1. heat
2. $E = \text{pole}$



1. cool
2. $E = 0$



- EO polymers are prepared by adding high concentrations of a “guest” chromophore to an amorphous “host” polymer.

- The composite is heated to the glass transition temperature to liquify the polymer and the poling field is applied to align the chromophores within the polymer matrix.

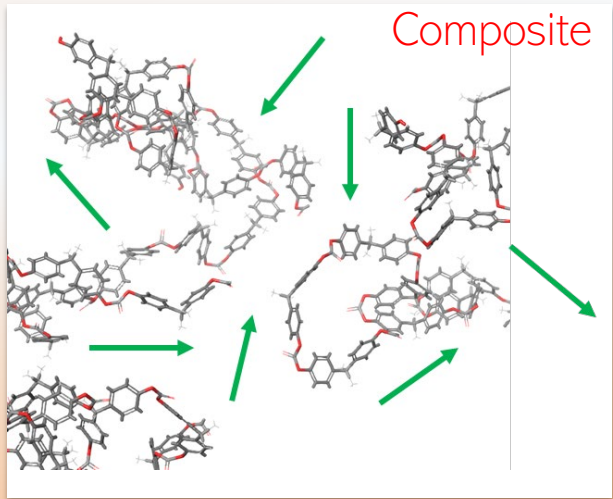
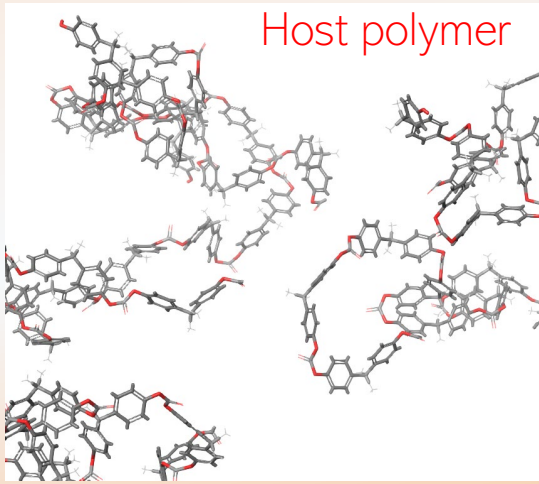
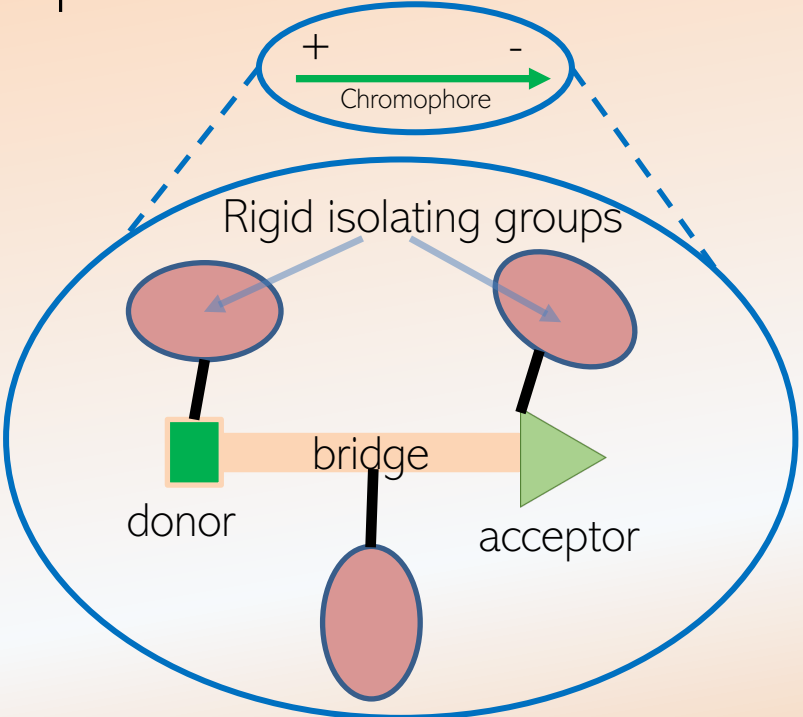
- The sample is cooled with the field applied to trap the poled order in the glassy state.

Barrier **h** is optimized by mix of chromophore and polymer



Design strategy for increasing barrier h at the molecular level

- Chromophores can be modified via synthetic organic chemistry to act as anti-plasticizers and increase the rigidity (*and barrier h*) of the composite polymer.



- Rigid isolating groups reduce dipolar interactions and *increase rigidity of polymer composite (h)*

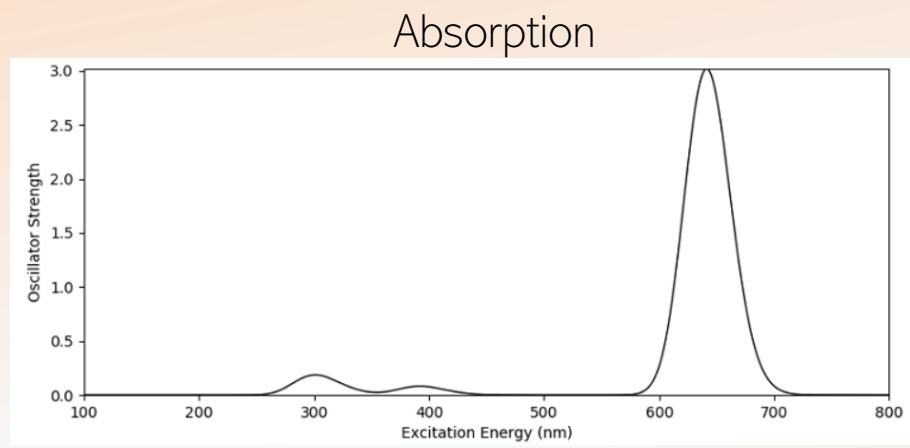
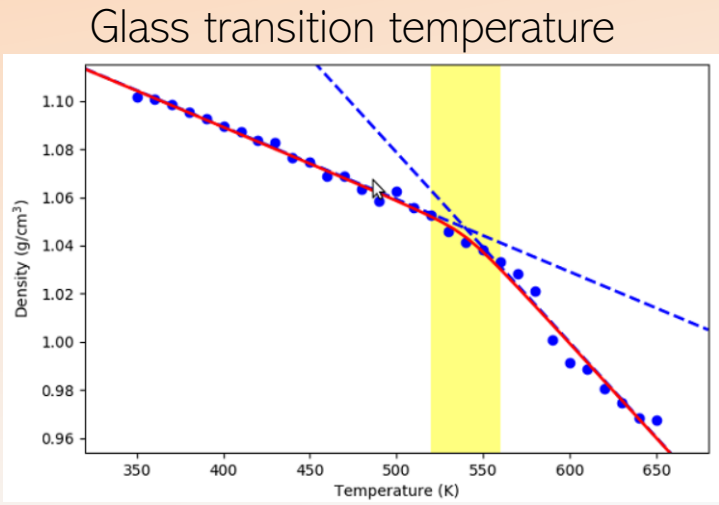
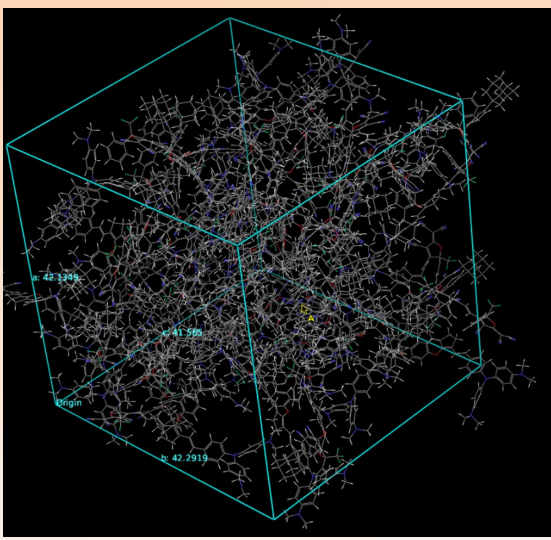
- Rigid, high glass transition temperature (T_g) *increases h*

- Rigid, high glass transition temperature (T_g) *increases h*

Molecular design is critical



Molecular Design: simulation guided design



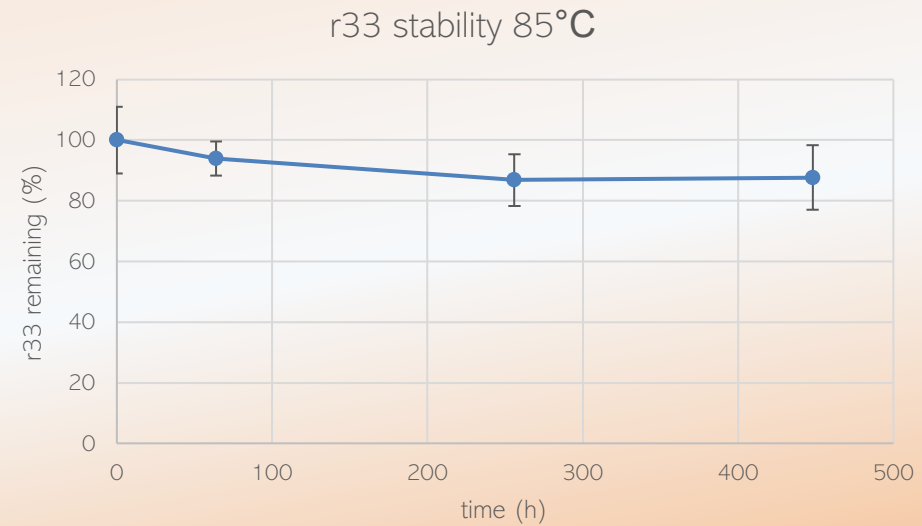
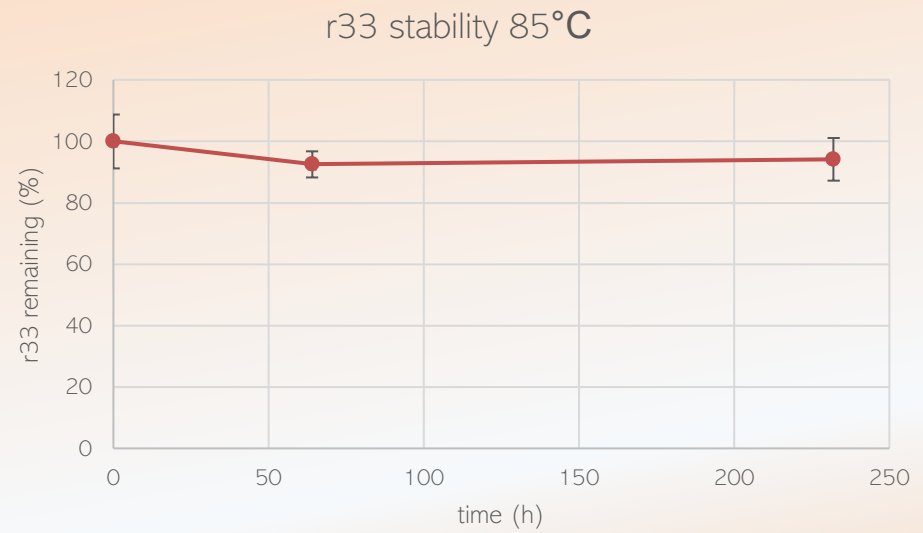
- Many interdependent parameters (besides rigidity of the composite) that need consideration: Dipole, Hyperpolarizability, Loss (absorption), Thermal stability, Poling efficiency, Solubility
- All of these are calculable with a combination of quantum mechanical (DFT) and molecular dynamics methods.
- Apply the same tools the pharmaceutical industry uses to engineer drugs and the display industry uses to engineer OLEDs to electro-optic polymers.

Molecular design through simulation tools increases cycles of learning



Higher stability of meta-stable state

- Improved temporal stability of r33 @ 85°C

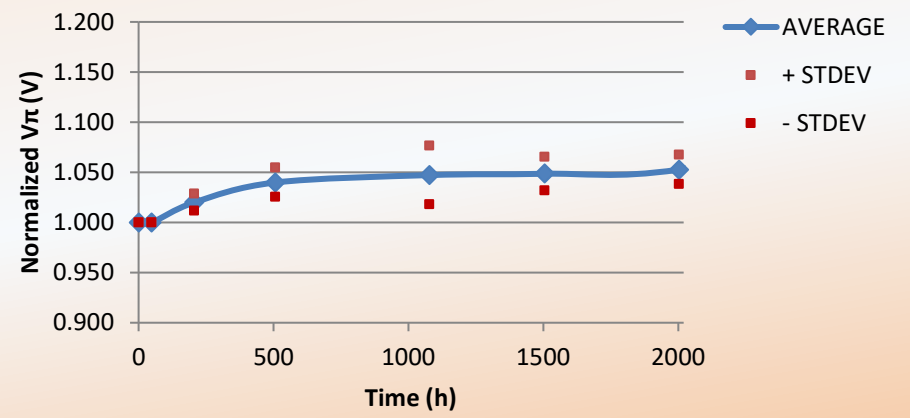
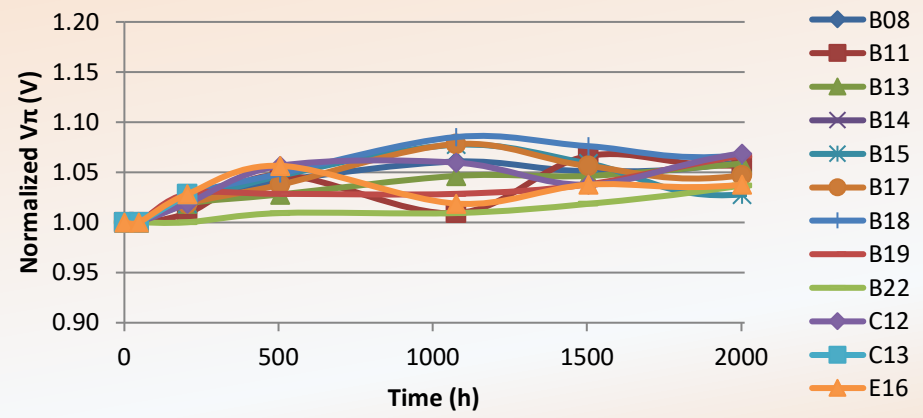


Result of increasing the barrier h of meta-stable state

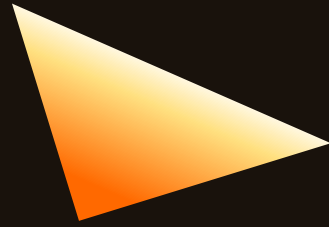


Higher stability of meta-stable state

- Improved temporal stability of V_{pi} @ 85°C



Result of increasing the barrier h of meta-stable state

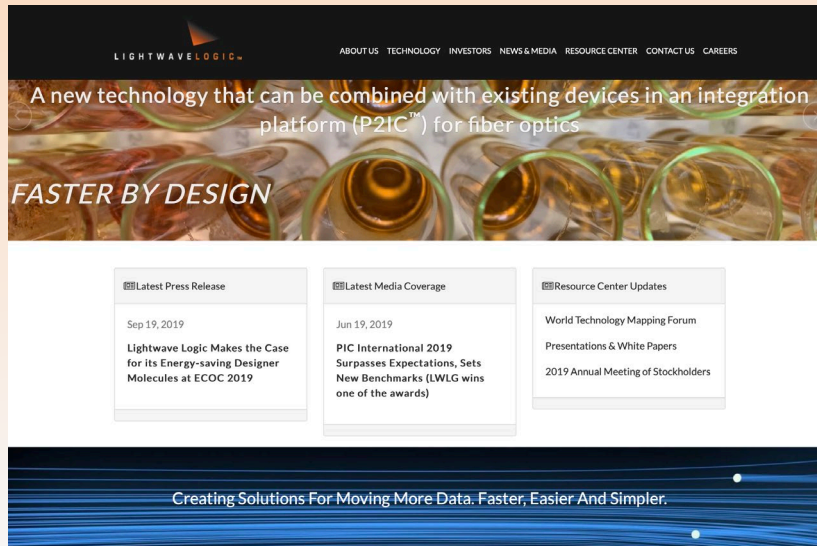


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Roadmap update

Slide presentation will be posted at website

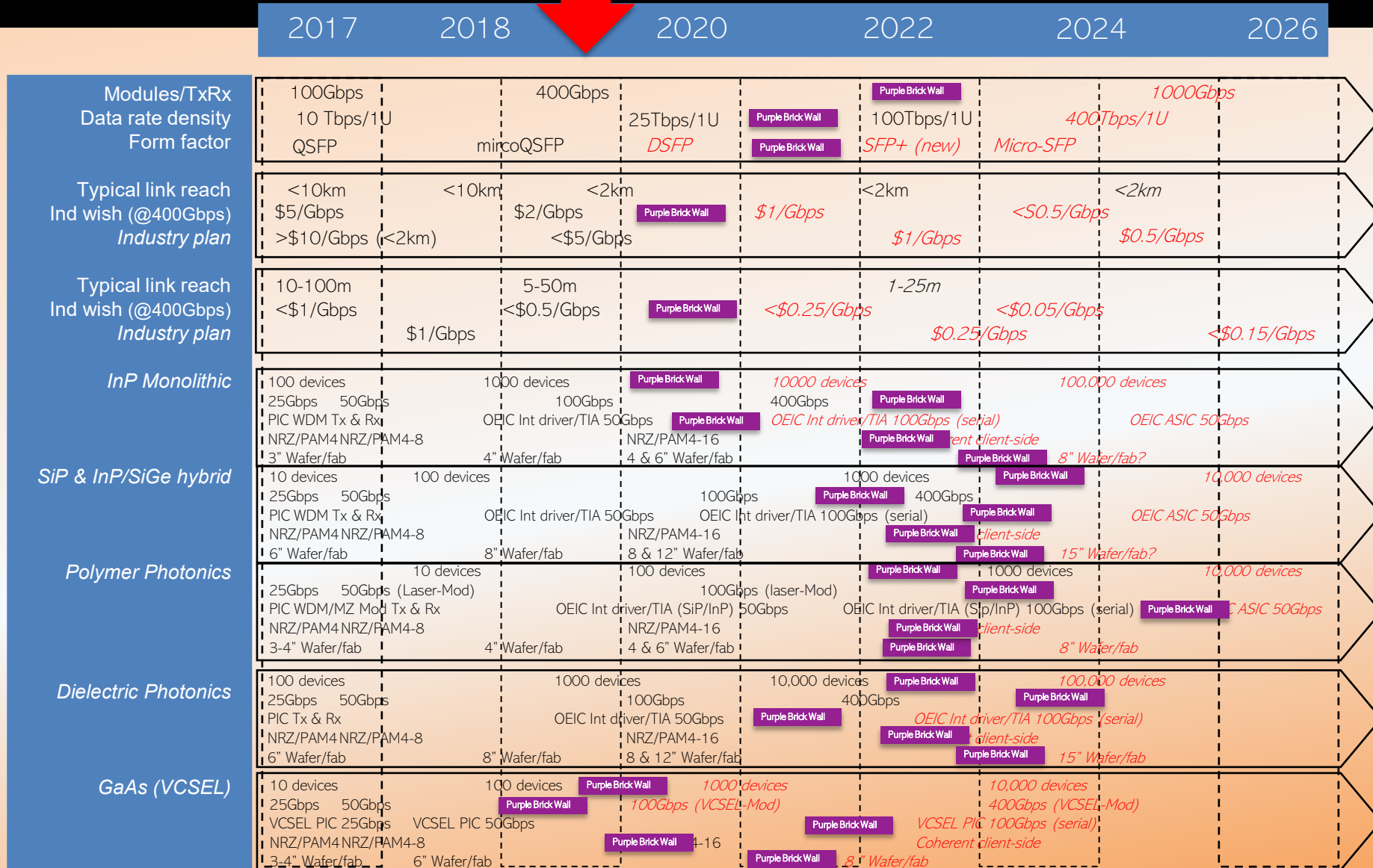


www.lightwavelogic.com

Sit back...relax...roadmaps *are very detailed...*

Roadmaps: What did we predict in 2016?

Purple Brick Wall = Technology cost barrier



Slanted Red Font: Major industry efforts are required for commercialization
 Source: Lightwave Logic

Actually pretty good → TxRx 400Gbps, <\$5/Gbps, 50Gbps+ devices



Purple Brick Wall = Technology cost barrier

	2017	2018	2020	2022	2024	2026
Modules/TxRx	100Gbps	400Gbps	1000Gbps	1000Gbps	1000Gbps	1000Gbps
Data rate density	10 Tbps/1U	25 Tbps/1U	100 Tbps/1U	400 Tbps/1U	1000 Tbps/1U	1000 Tbps/1U
Form factor	QSFP	microQSFP	DSFP	SFP+ (new)	Micro-SFP	Micro-SFP
Typical link reach	<10km	<10km	<2km	<2km	<2km	<2km
Ind wish (@400Gbps)	\$5/Gbps	\$2/Gbps	\$1/Gbps	\$1/Gbps	<\$0.5/Gbps	<\$0.5/Gbps
Industry plan	>\$10/Gbps (<2km)	<\$5/Gbps	Purple Brick Wall	\$1/Gbps	<\$0.5/Gbps	\$0.5/Gbps
Typical link reach	10-100m	5-50m	1-25m	1-25m	1-25m	1-25m
Ind wish (@400Gbps)	<\$1/Gbps	<\$0.5/Gbps	<\$0.25/Gbps	\$0.25/Gbps	<\$0.05/Gbps	<\$0.15/Gbps
Industry plan	\$1/Gbps	<\$0.5/Gbps	Purple Brick Wall	<\$0.25/Gbps	\$0.25/Gbps	<\$0.15/Gbps
InP Monolithic	100 devices	1000 devices	10000 devices	10000 devices	100000 devices	100000 devices
25Gbps 50Gbps	PIC WDM Tx & Rx	OEIC Int driver/TIA 50Gbps	OEIC Int driver/TIA 100Gbps (serial)	OEIC Int driver/TIA 100Gbps (serial)	OEIC ASIC 50Gbps	OEIC ASIC 50Gbps
NRZ/PAM4 NRZ/PAM4-8	3" Wafer/fab	4" Wafer/fab	4 & 6" Wafer/fab	client-side	8" Wafer/fab?	8" Wafer/fab?
SiP & InP/SiGe hybrid	10 devices	100 devices	1000 devices	1000 devices	10000 devices	10000 devices
25Gbps 50Gbps	PIC WDM Tx & Rx	OEIC Int driver/TIA 50Gbps	OEIC Int driver/TIA 100Gbps (serial)	OEIC Int driver/TIA 100Gbps (serial)	OEIC ASIC 50Gbps	OEIC ASIC 50Gbps
NRZ/PAM4 NRZ/PAM4-8	6" Wafer/fab	8" Wafer/fab	8 & 12" Wafer/fab	client-side	15" Wafer/fab?	15" Wafer/fab?
Polymer Photonics	10 devices	100 devices	1000 devices	1000 devices	10000 devices	10000 devices
25Gbps 50Gbps (Laser-Mod)	PIC WDM/MZ Mod Tx & Rx	OEIC Int driver/TIA (SiP/InP) 50Gbps	OEIC Int driver/TIA (SiP/InP) 100Gbps (serial)	OEIC Int driver/TIA (SiP/InP) 100Gbps (serial)	OEIC ASIC 50Gbps	OEIC ASIC 50Gbps
NRZ/PAM4 NRZ/PAM4-8	3-4" Wafer/fab	4" Wafer/fab	4 & 6" Wafer/fab	client-side	8" Wafer/fab	8" Wafer/fab
Dielectric Photonics	100 devices	1000 devices	10000 devices	10000 devices	100000 devices	100000 devices
25Gbps 50Gbps	PIC Tx & Rx	OEIC Int driver/TIA 50Gbps	OEIC Int driver/TIA 100Gbps (serial)	OEIC Int driver/TIA 100Gbps (serial)	OEIC ASIC 50Gbps	OEIC ASIC 50Gbps
NRZ/PAM4 NRZ/PAM4-8	6" Wafer/fab	8" Wafer/fab	8 & 12" Wafer/fab	client-side	15" Wafer/fab	15" Wafer/fab
GaAs (VCSEL)	10 devices	100 devices	1000 devices	10000 devices	10000 devices	10000 devices
25Gbps 50Gbps	VCSEL PIC 25Gbps	VCSEL PIC 50Gbps	VCSEL PIC 100Gbps (serial)	VCSEL PIC 100Gbps (serial)	VCSEL PIC 100Gbps (serial)	VCSEL PIC 100Gbps (serial)
NRZ/PAM4 NRZ/PAM4-8	3-4" Wafer/fab	6" Wafer/fab	4-16" Wafer/fab	8" Wafer/fab	8" Wafer/fab	8" Wafer/fab

Slanted Red Font: Major industry efforts are required for commercialization
 Source: Lightwave Logic

New draft in 2019 → Where are we going?

Purple Brick Wall = Technology cost barrier

	2019	2020	2022	2024	2026	2028
Modules/TxRx	400Gbps	800Gbps	1600Gbps	3200Gbps		
Data rate density	25 Tbps/1U		100Tbps/1U	400Tbps/1U	1600Tbps/1U	
Form factor	Q/OSFP	OSFP/OBO/CP	OBO/CP	Co-Pkg/CoB	Micro-Co-Pkg/CoB	
Typical link reach	<10km	<10km	<2km	<2km	<2km	<2km
Ind wish (@400Gbps)	\$2/Gbps	\$1/Gbps	\$0.5/Gbps	\$0.5/Gbps	<\$0.2/Gbps	\$0.2/Gbps
Industry plan	>\$5/Gbps (<2km)	<\$2/Gbps				
Typical link reach	10-100m	5-50m	1-25m	1-25m		
Ind wish (@400Gbps)	<\$1/Gbps	<\$0.5/Gbps	<\$0.25/Gbps	<\$0.25/Gbps	<\$0.05/Gbps	<\$0.15/Gbps
Industry plan	\$1/Gbps					
InP Monolithic	100 devices 25GHz 50GHz PIC WDM Tx & Rx (30GHz) NRZ/PAM4 NRZ/PAM4-8 3" Wafer/fab	1000 devices 70GHz OEIC Int driver/TIA 50Gbps (50GHz) NRZ/PAM4-16 4" Wafer/fab	10000 devices 90GHz OEIC Int driver/TIA 100Gbps (70GHz) Coherent client-side 4 & 6" Wafer/fab	100,000 devices 100GHz OEIC ASIC 50Gbps (50GHz) 8" Wafer/fab?		
SiP & InP/SiGe hybrid	10 devices 25GHz 50GHz PIC WDM Tx & Rx (30GHz) NRZ/PAM4 NRZ/PAM4-8 6" Wafer/fab	100 devices 70GHz (100Gbps) OEIC Int driver/TIA 50Gbps (50GHz) NRZ/PAM4-16 8" Wafer/fab	1000 devices 70GHz (400Gbps) OEIC Int driver/TIA 100Gbps (serial) Coherent DSP-less 8 & 12" Wafer/fab	10,000 devices 70GHz (s) OEIC Int driver/TIA (SiP/InP) 15" Wafer/fab?		
Polymer Photonics	10 devices 25GHz 50GHz (Laser-Mod) PIC WDM/MZ Mod Tx & Rx NRZ/PAM4 NRZ/PAM4-8 3-4" Wafer/fab	1000 devices 70GHz (laser-Mod) OEIC Int driver/TIA (SiP/InP) NRZ/PAM4-16 4" Wafer/fab	10,000 devices 100GHz (150Gbps serial) OEIC Int driver/TIA (SiP/InP) 70GHz (s) 8" Wafer/fab	100,000 devices 70GHz (400Gbps) OEIC Int driver/TIA 70GHz 15" Wafer/fab		
Dielectric Photonics	100 devices 25GHz 50GHz PIC Tx & Rx NRZ/PAM4 NRZ/PAM4-8 6" Wafer/fab	1000 devices 70GHz OEIC Int driver/TIA 50GHz NRZ/PAM4-16 8" Wafer/fab	10,000 devices 70GHz OEIC Int driver/TIA 70GHz Coherent client-side 8 & 12" Wafer/fab	100,000 devices 70GHz (400Gbps) OEIC Int driver/TIA 70GHz 15" Wafer/fab		
GaAs (VCSEL)	100 devices 25GHz 50GHz VCSEL PIC 25GHz NRZ/PAM4 NRZ/PAM4-8 6" Wafer/fab	1000 devices 70GHz (VCSEL-Mod) VCSEL PIC 70GHz (100Gbps) NRZ/PAM4-16 8" Wafer/fab	10,000 devices 70GHz (VCSEL-Mod) VCSEL PIC 70GHz (100Gbps) Coherent client-side 8" Wafer/fab	100,000 devices 70GHz (VCSEL-Mod) VCSEL PIC 70GHz (100Gbps) Coherent client-side		

Slanted Red Font: Major industry efforts are required for commercialization

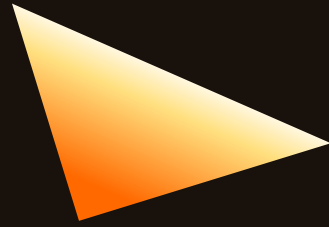
Source: Lightwave Logic

800 and 1600Gbps; very high bandwidth 70GHz, co-packaging, low power, hybrid integration, low \$/Gbps



	2019	2020	2022	2024	2026	2028
Modules/TxRx	400Gbps	800Gbps	1600Gbps	3200Gbps		
Data rate density	25 Tbps/1U		100Tbps/1U	400Tbps/1U	1600Tbps/1U	
Form factor	Q/OSFP	OSFP/OBO/CP	OBO/CP	Co-Pkg/CoB	Micro-Co-Pkg/CoB	
Typical link reach	<10km	<10km	<2km	<2km	<2km	<2km
Ind wish (@400Gbps)	\$2/Gbps	\$1/Gbps	\$0.5/Gbps	\$0.5/Gbps	<\$0.2/Gbps	\$0.2/Gbps
Industry plan	>\$5/Gbps (<2km)	<\$2/Gbps				
Typical link reach	10-100m	5-50m	1-25m	1-25m		
Ind wish (@400Gbps)	<\$1/Gbps	<\$0.5/Gbps	<\$0.25/Gbps	<\$0.25/Gbps	<\$0.05/Gbps	<\$0.15/Gbps
Industry plan	\$1/Gbps					
InP Monolithic	100 devices 25GHz 50GHz PIC WDM Tx & Rx (30GHz) NRZ/PAM4 NRZ/PAM4-8 3" Wafer/fab	1000 devices 70GHz OEIC Int driver/TIA 50Gbps (50GHz) NRZ/PAM4-16 4" Wafer/fab	10000 devices 90GHz OEIC Int driver/TIA 100Gbps (70GHz) Coherent client-side 4 & 6" Wafer/fab	100,000 devices 100GHz OEIC ASIC 50Gbps (50GHz) 8" Wafer/fab?		
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Polymer Photonics	10 devices 25GHz 50GHz (Laser-Mod) PIC WDM/MZ Mod Tx & Rx NRZ/PAM4 NRZ/PAM4-8 3-4" Wafer/fab	1000 devices 70GHz (laser-Mod) OEIC Int driver/TIA (SiP/InP) 50GHz NRZ/PAM4-16 4" Wafer/fab	10,000 devices 100GHz (150Gbps serial) OEIC Int driver/TIA (SiP/InP) 70GHz (serial) Coherent client-side 8" Wafer/fab	100,000 devices 70GHz (400Gbps) OEIC Int driver/TIA 70GHz 15" Wafer/fab		
Dielectric Photonics	100 devices 25GHz 50GHz PIC Tx & Rx NRZ/PAM4 NRZ/PAM4-8 6" Wafer/fab	1000 devices 70GHz OEIC Int driver/TIA 50GHz NRZ/PAM4-16 8" Wafer/fab	10,000 devices 70GHz OEIC Int driver/TIA 50GHz NRZ/PAM4-16 8 & 12" Wafer/fab	100,000 devices 70GHz (400Gbps) OEIC Int driver/TIA 70GHz 15" Wafer/fab		
GaAs (VCSEL)	100 devices 25GHz 50GHz VCSEL PIC 25GHz NRZ/PAM4 NRZ/PAM4-8 6" Wafer/fab	1000 devices 70GHz (VCSEL-MZ) VCSEL PIC 70GHz (100Gbps) NRZ/PAM4-16 8" Wafer/fab	10,000 devices 70GHz (VCSEL-MZ) VCSEL PIC 70GHz (100Gbps) Coherent client-side 8" Wafer/fab	100,000 devices 70GHz (VCSEL-MZ) VCSEL PIC 70GHz (100Gbps) Coherent client-side 8" Wafer/fab		

Slanted Red Font: Major industry efforts are required for commercialization
Source: Lightwave Logic



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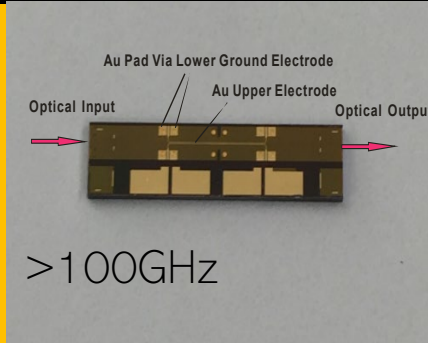
OTCQB: LWLG

Summary

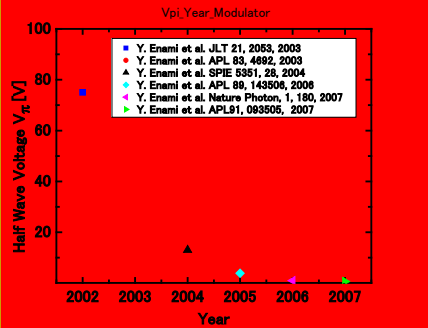


Electro-optic polymer example

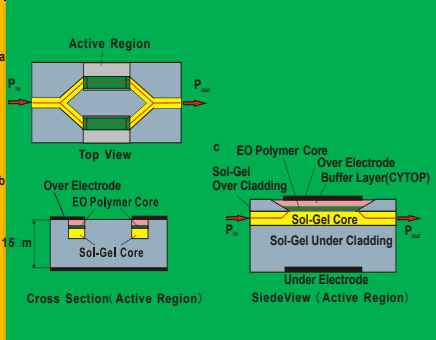
Faster devices (100GHz+)



Lower Power (Low voltage)



Low cost (Easy fab)



Robust (Stable)

Test Item	Test Description	Specification: Method or Conditions	Sample Data	Passed Y/N
HTOL	High temperature operation life time test	Telcordia GR-468_CORE02 3.3.2.1; 2000 hrs at power, driver, bias and T _a = 85°C	11	Y
Low Temperature Storage	Storage only in low temperature	Telcordia GR-468_CORE02 3.3.2.1 -40°C, 72 Hour	11	Y
Mechanical Shock	Apply mechanical shocks to device	Telcordia GR-468_CORE02 3.3.1.1; MIL-STD-883 Method 2002.3	7	Y
Vibration	Apply vibration to device	GR-468_CORE02 3.3.1.1; MIL-STD-883 Method 2007.2	6	Y
Thermal Shock	Sudden exposure to extreme changes in temperature	Telcordia GR-468_CORE02 3.3.1.2; MIL-STD-883 Method 1011.9	11	Y
Fiber Twist	Twist fiber pigtail	Telcordia GR-468_CORE02 3.3.1.3; FOTF 34	8	Y
Fiber Side Pull	Pull fiber pigtail	Telcordia GR-468_CORE02 3.3.1.3.2; GR-326-CORE 4.4.3.5	8	Y
Cable Retention	Apply force to the cable	Telcordia GR-468_CORE02 3.3.1.3.2; FOTF 5	11	Y

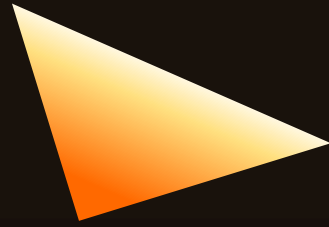
Our EO polymers enable *radical innovation...*

Summary

- Speed today...
 - We as an industry are struggling with >50GHz analogue bandwidth. Higher speeds has to come from increasing complexity of modulation schemes and electronics
 - *We can use polymer modulators for 70GHz analogue bandwidth (for 100Gbps NRZ data, 200Gbaud PAM4 data)*
 - *E.g. 100Gbps single lane NRZ, 400Gbps with 4 lanes NRZ, 800 Gbps with 4 lanes PAM4*
- Power today...
 - We as an industry are struggling to bring voltage levels at 70GHz down to 1 Volt for any modulator design
 - *~1V means we can eliminate drivers, use direct drive from CMOS circuitry*
- Cost today...
 - MZ modulators are expensive designs using InP, SiPh, LiNbO₃
 - *Spin-on fab compatible Polymer MZ fabrication is cost effective Mach-Zehnder fits in OSFP-like transceiver footprints*
 - *Hybrid integration possible with InP, Si photonics, etc.*
- Robust today...
 - Industry expects standard Telcordia specifications for MZ modulators
 - *Polymers have achieved GR-468 and are continually improving their stability specifications*
- Roadmaps...
 - Predictions have been fairly accurate to date...challenging times ahead



Polymers are quickly becoming an important platform...



LIGHTWAVE LOGIC™

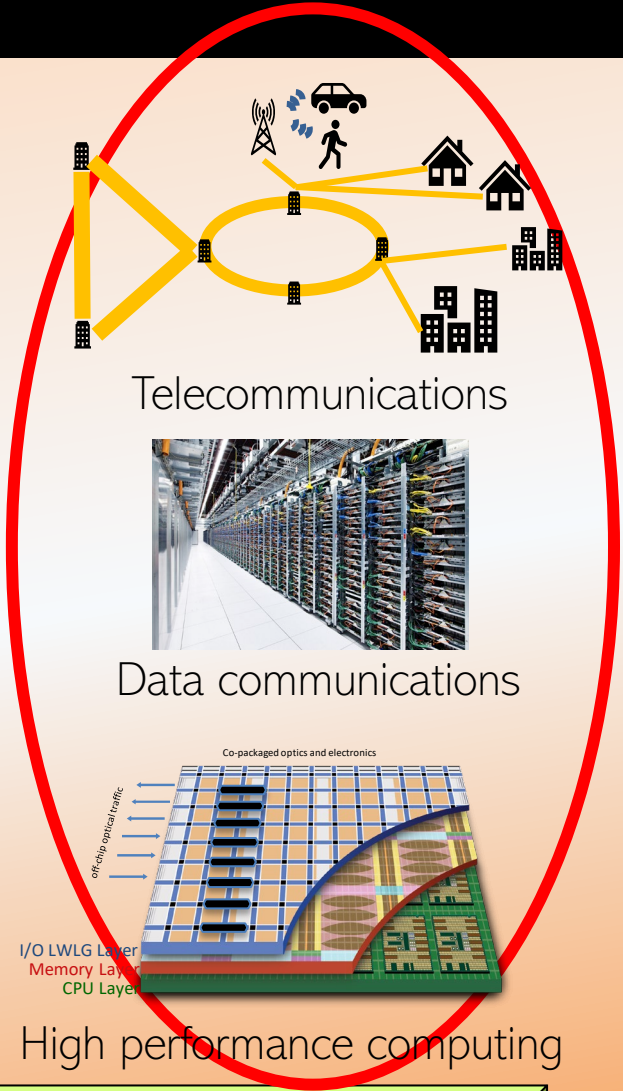
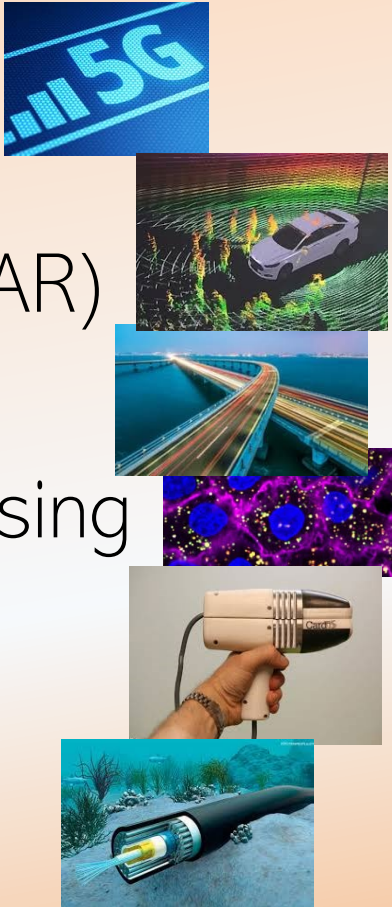
OTCQB: LWLG

Thank you
Symbol OTCQB: LWLG



Many opportunities, however, all need robustness

- 5G systems
- RF over fiber
- Automotive (LIDAR)
- Optical sensing
- Bio-photonic sensing
- Medical
- Instrumentation
- Others...



Maturity (and robustness) in Fiber Comm enables other markets